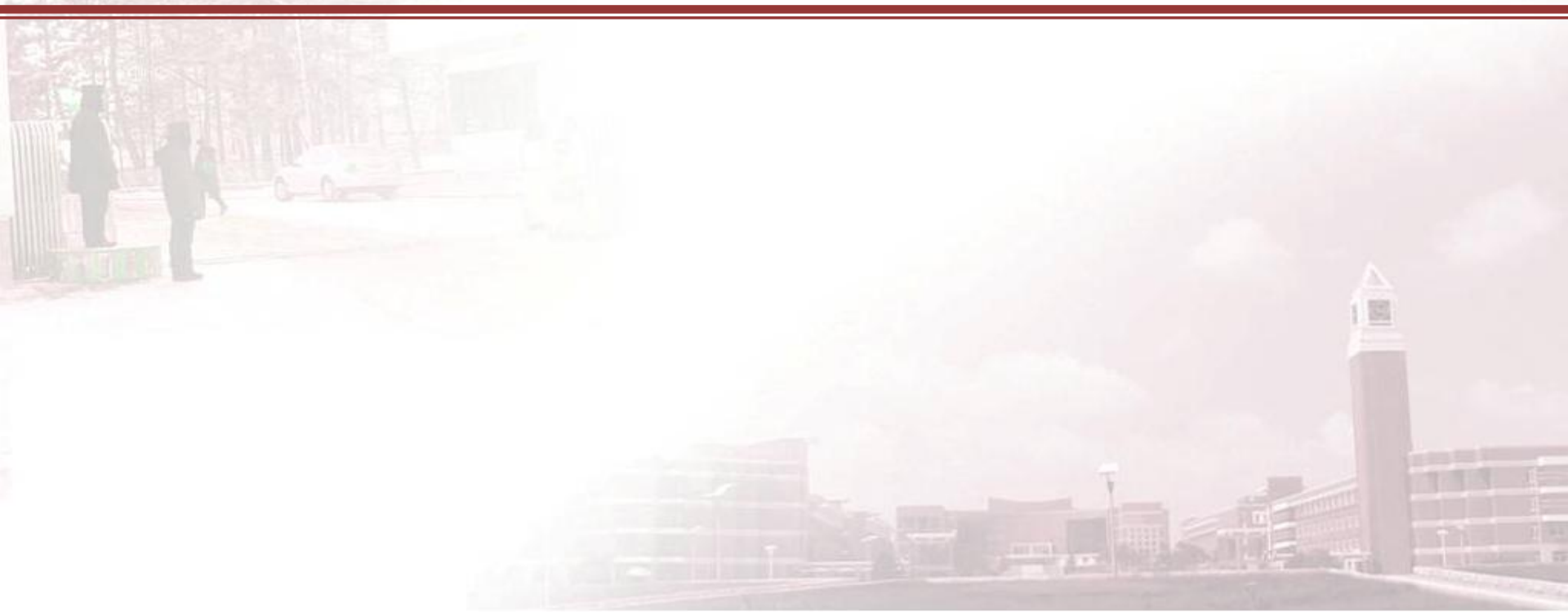
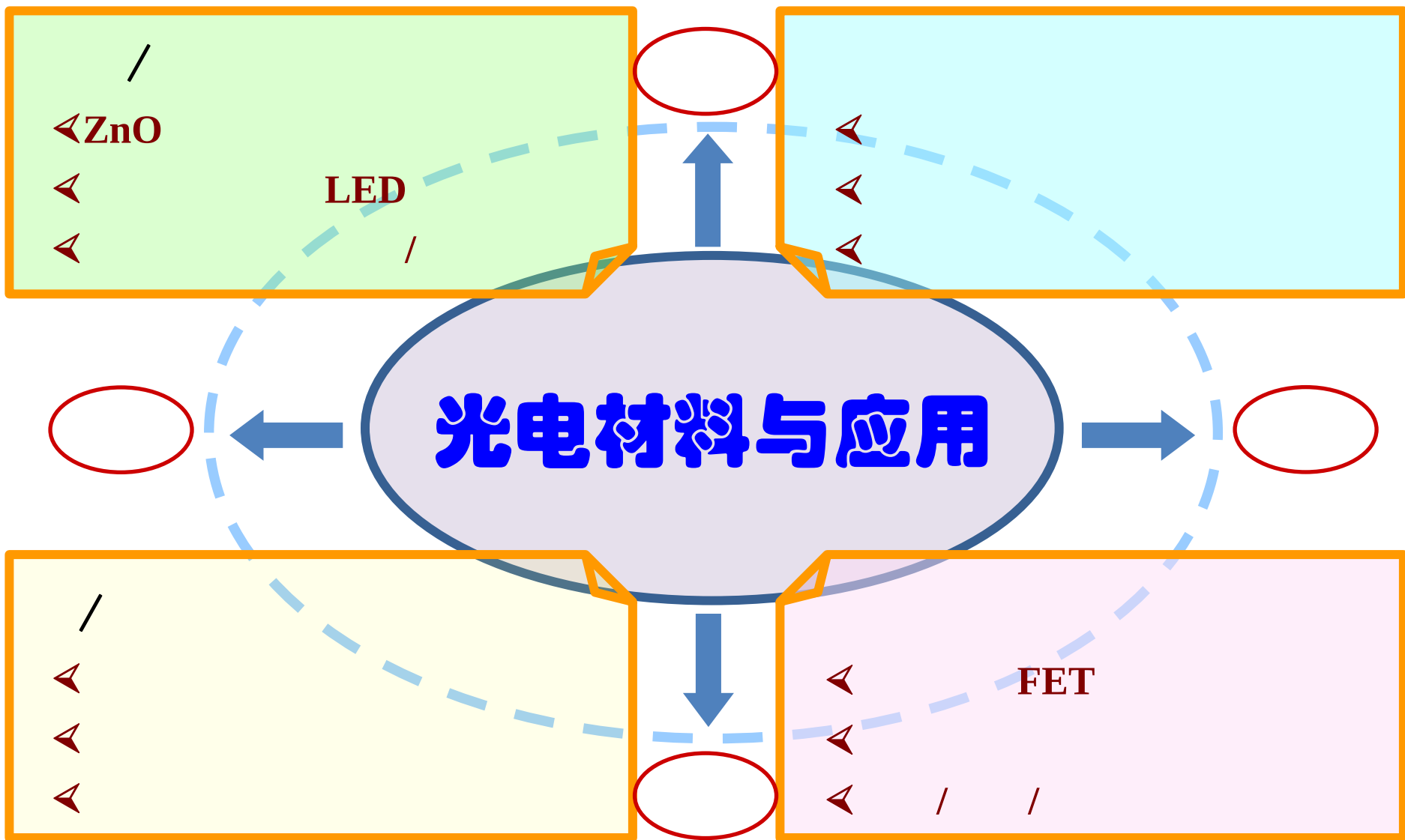




东北师范大学

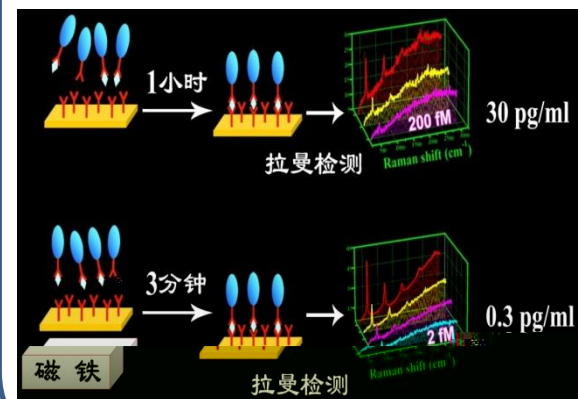
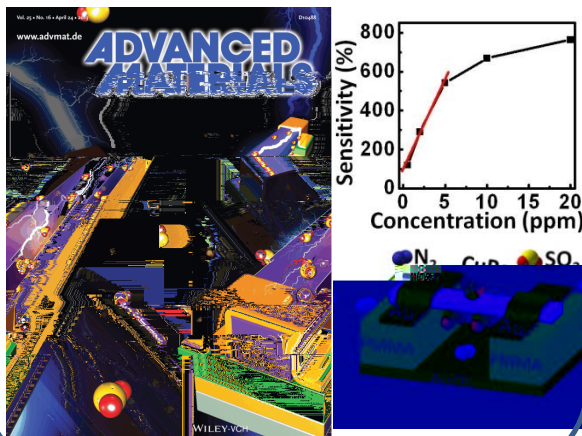
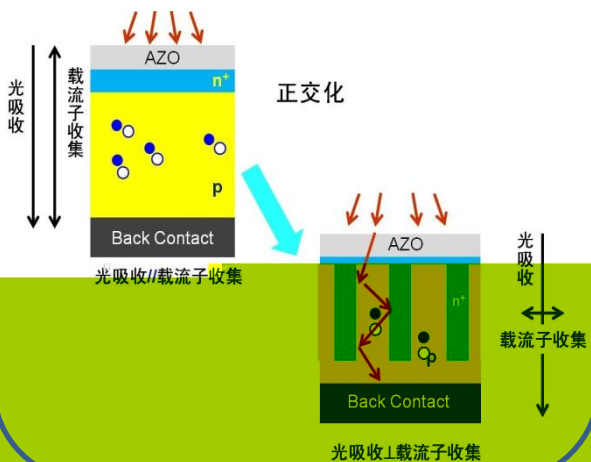
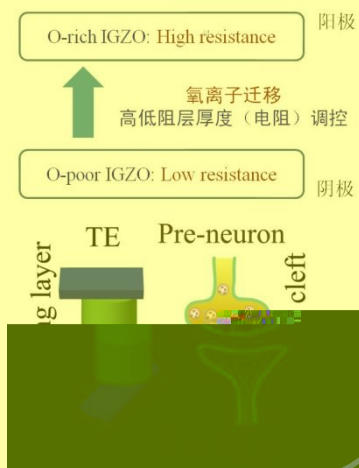
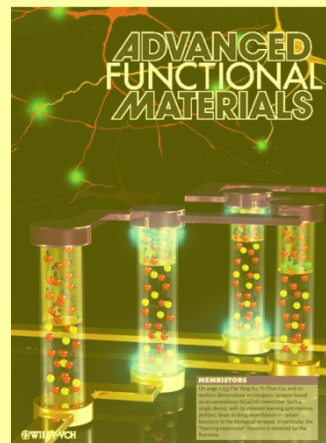
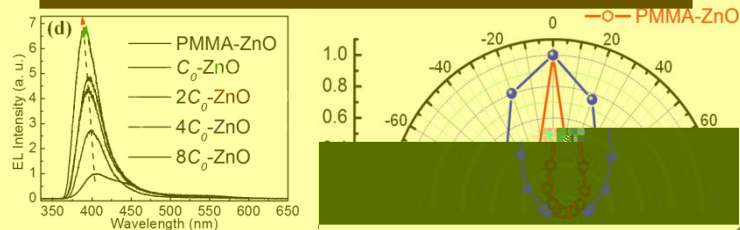
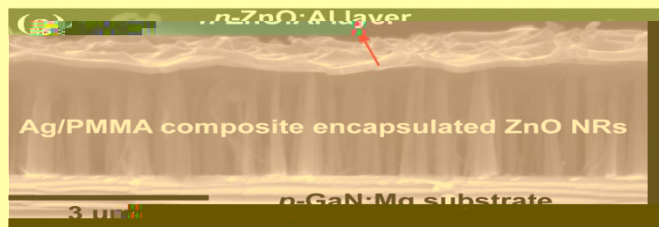
ZnO





研究方向

纳米材料——优异的光/电特性，独特的物理/化学性质



内容提纲

ZnO

LED/LD



LED/LD

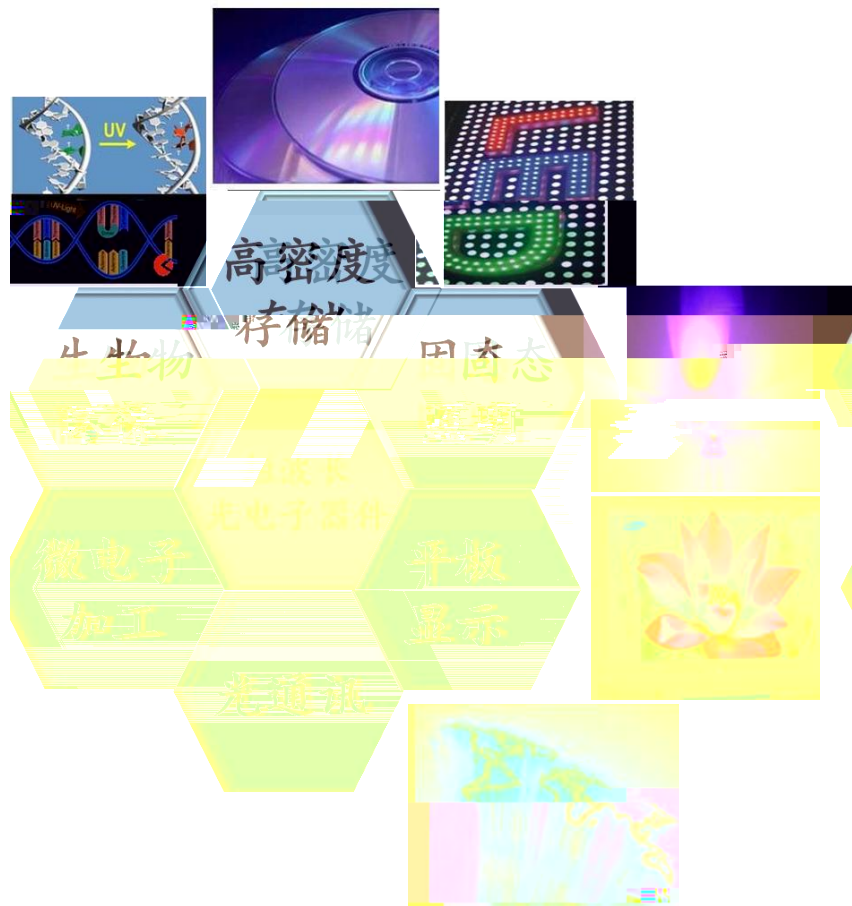
ZnO



ZnO

ZnO

短波长光发射器件



研究目标:

高效、稳定
ZnO紫外LED/LD

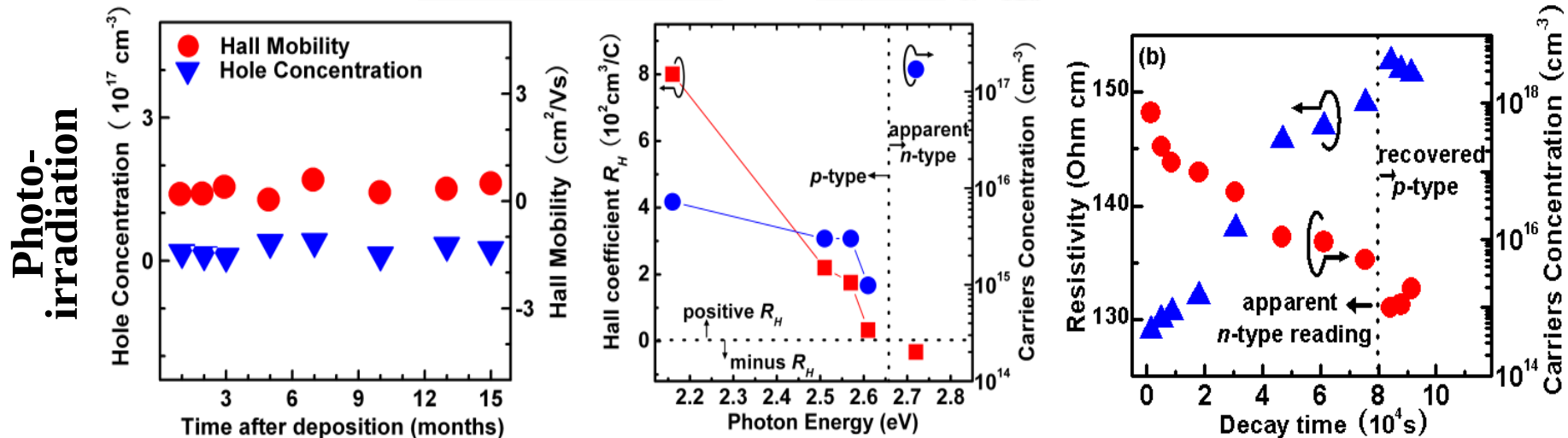
同质结器件:

1. p-type ZnO 稳定性、可重复性
2. p-type ZnO 质量, 缺陷发射为主降低紫外效率



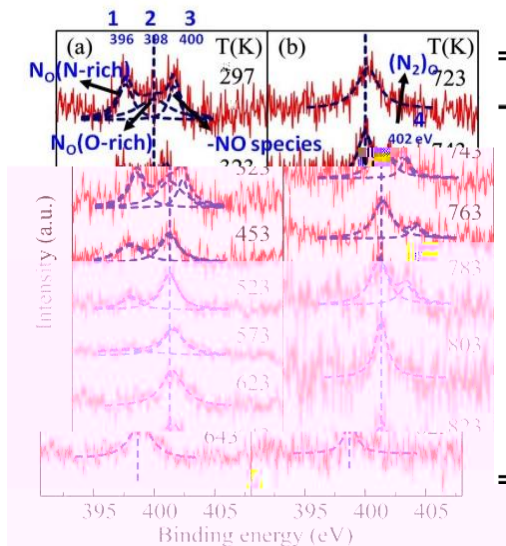
P-type

Stability of p-type ZnO



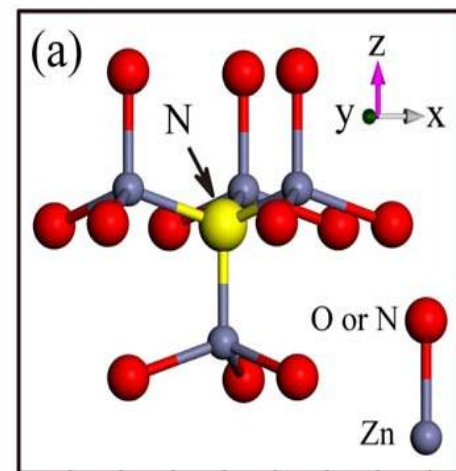
Appl. Phys. Lett. 92, 052106 (2008)

Thermal



Peak	N 1s	assignment (reference)	Our assignment	Stabilities
1	~396 eV	N-Zn bond or N_0 ^(7,11) , polarized triply bonded CN ⁽¹⁶⁾ , N-O ⁽¹⁷⁾	N-Zn at nitrogen rich environment	unstable
2	~398 eV	N-Zn bond or N_0 ^(2,13,14,16-18) , C-N species ⁽⁷⁾ , N-H ^(9,10)	N-Zn at oxygen rich environment	Stable to 723 K
3	~400 eV	C-N species ^(7,10,16) , N-H ^(13,14,16) , oxynitride ⁽⁸⁾	-NO species	unstable
4	~402 eV	$(N_2)_0$ ^(7,10,14,16) , nitrite ^(2,8)	$(N_2)_0$	unstable

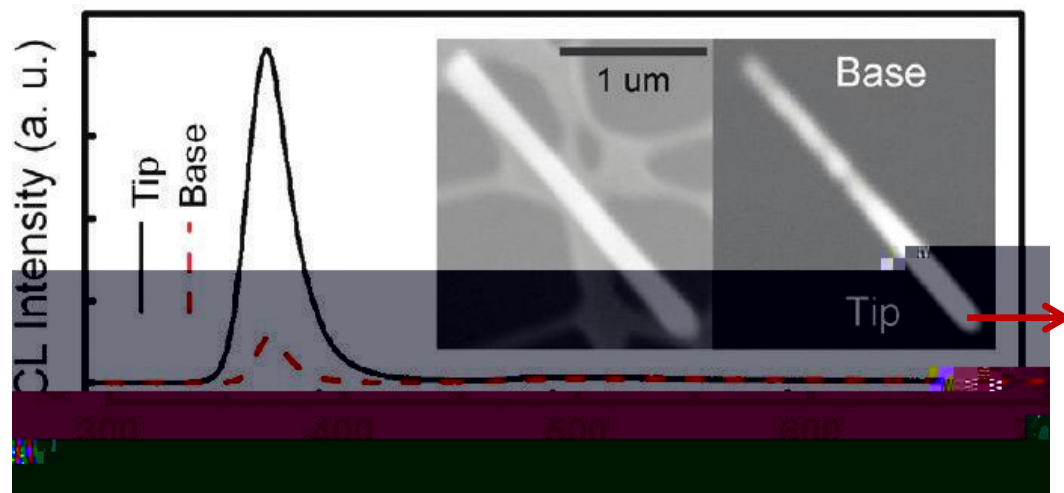
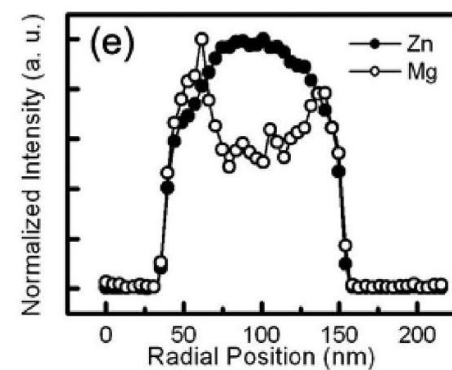
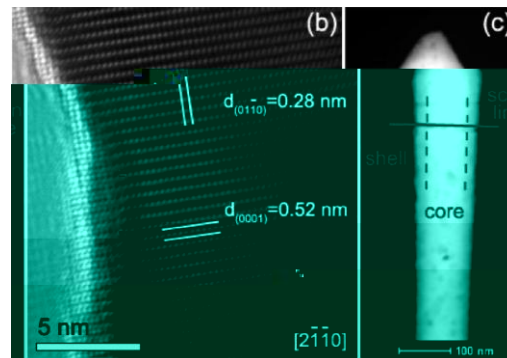
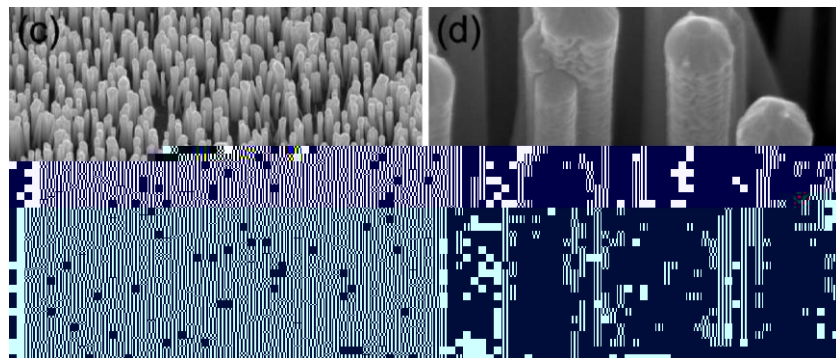
Appl. Phys. Lett. 95, 191903 (2009)

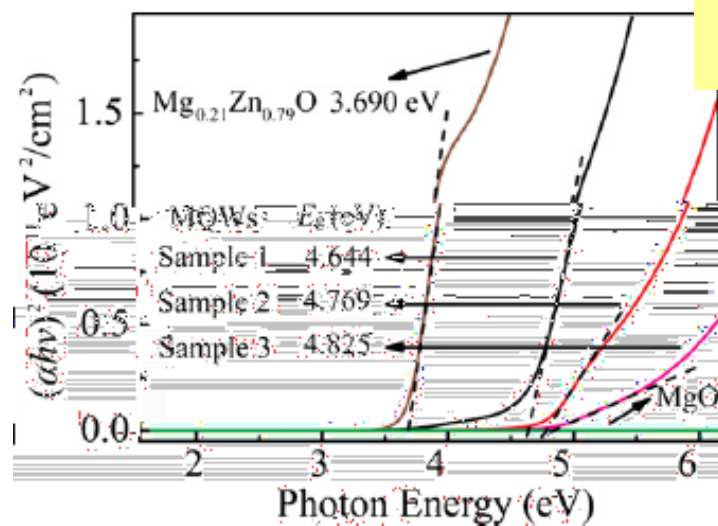


异质结器

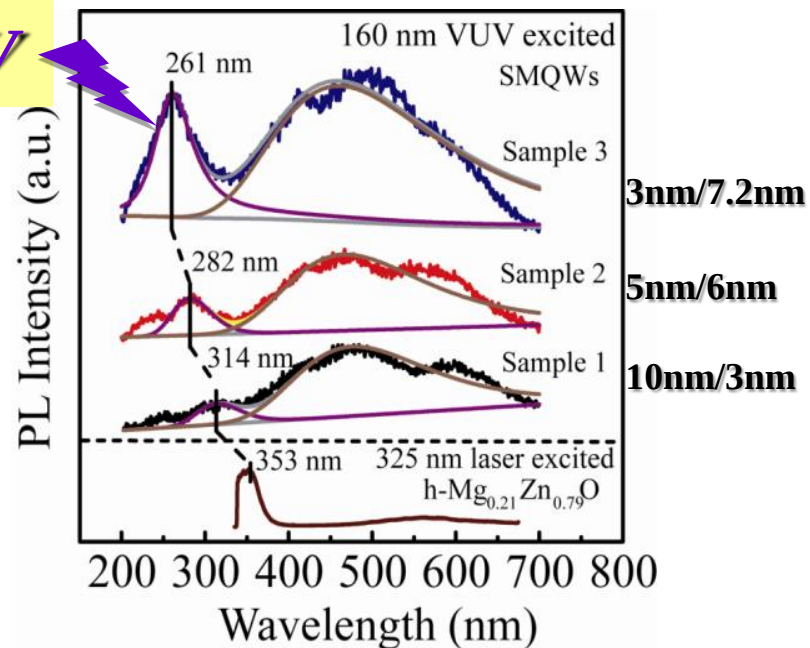
主

研究工作--ZnO纳米线异质结构





DUV



$$\Delta E_{\text{stress}} = \beta \sigma$$

Sample	α (°)	$d_{\text{nan}}(\text{\AA})$	$\sigma(\text{GPa})$	$\Delta E_{\text{exc}}(\text{meV})$	$\Delta E_{\text{exc}}(\text{meV})$
859	1	4.261	88.74	2.980	31.7
913	2	4.249	88.60	2.967	33.7
921	3	4.244	88.66	2.965	34.0

[Appl. Phys. Lett. 102, 031905 \(2013\)](#)

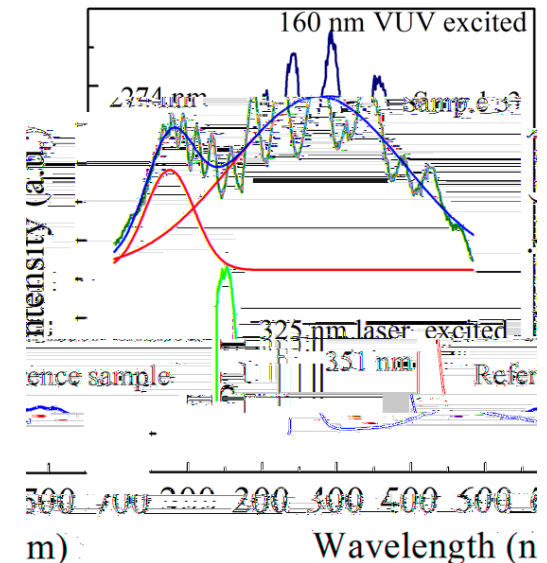
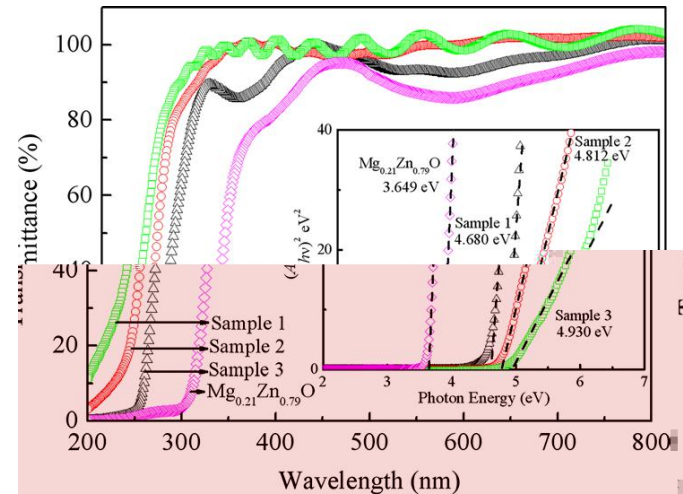
[J. Alloy. Compd. 513, 399 \(2012\)](#)

$$\frac{1}{d_{(hkl)}^2} = \frac{h^2 + k^2 - 2hk \cos \gamma}{a^2 \sin^2 \gamma} + \frac{l^2}{c^2}$$

$$\sigma = -\frac{Y}{\nu} \frac{d_{(hkl)} - d'_{(hkl)}}{d'_{(hkl)}}$$

$$E_{\text{stress}} = a_0 (\ln V - \ln V_0)$$

Sample	$a / \text{\AA}$	$c / \text{\AA}$	$\lambda / \text{\AA}$	E_g / meV	$E_{\text{stress}} / \text{meV}$
1	4.255	4.190	88.76	1031	184
2	4.244	4.174	88.66	1163	257
3	4.232	4.140	88.44	1281	370



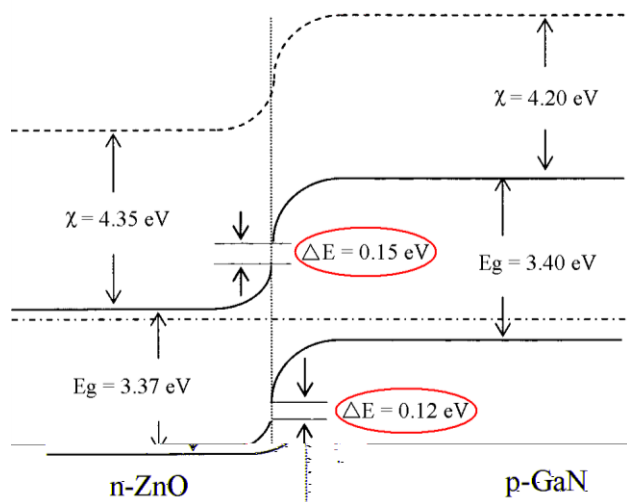
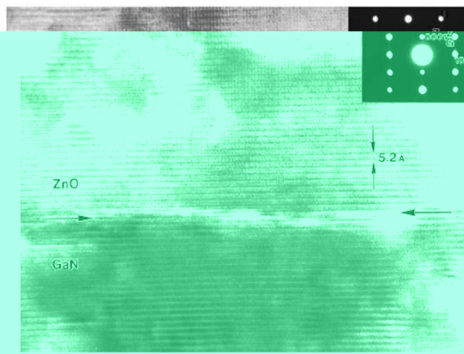
[*Appl. Phys. Lett.* 102, 031905 \(2013\)](#)

[*J. Alloy. Compd.* 513, 399 \(2012\)](#)

p-GaN/i-ZnO/n-ZnO 异质结 ZnO UV LEDs

p-type: Si, NiO, **GaN**, organics, etc.

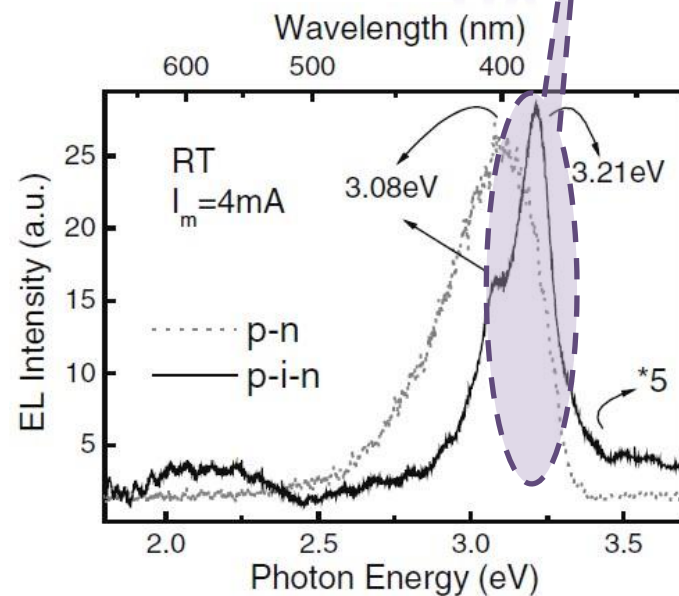
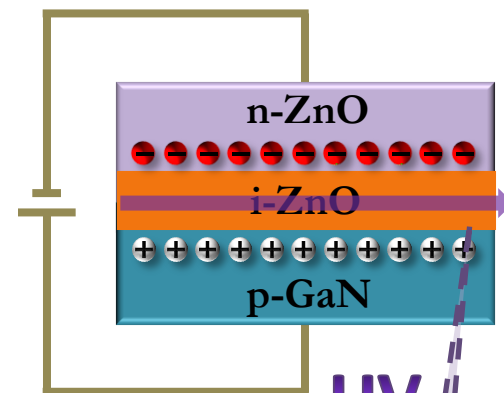
material	ZnO	GaN
crystal structure	wurtzite	wurtzite
lattice constant (nm)	$a=0.325$ $c=0.521$	$a=0.319$ $c=0.519$
band gap (eV)	3.37	3.39
lattice mismatch	1.9%	



导带失配和价带失配近似相等

电子和空穴克服相近势垒实现注入

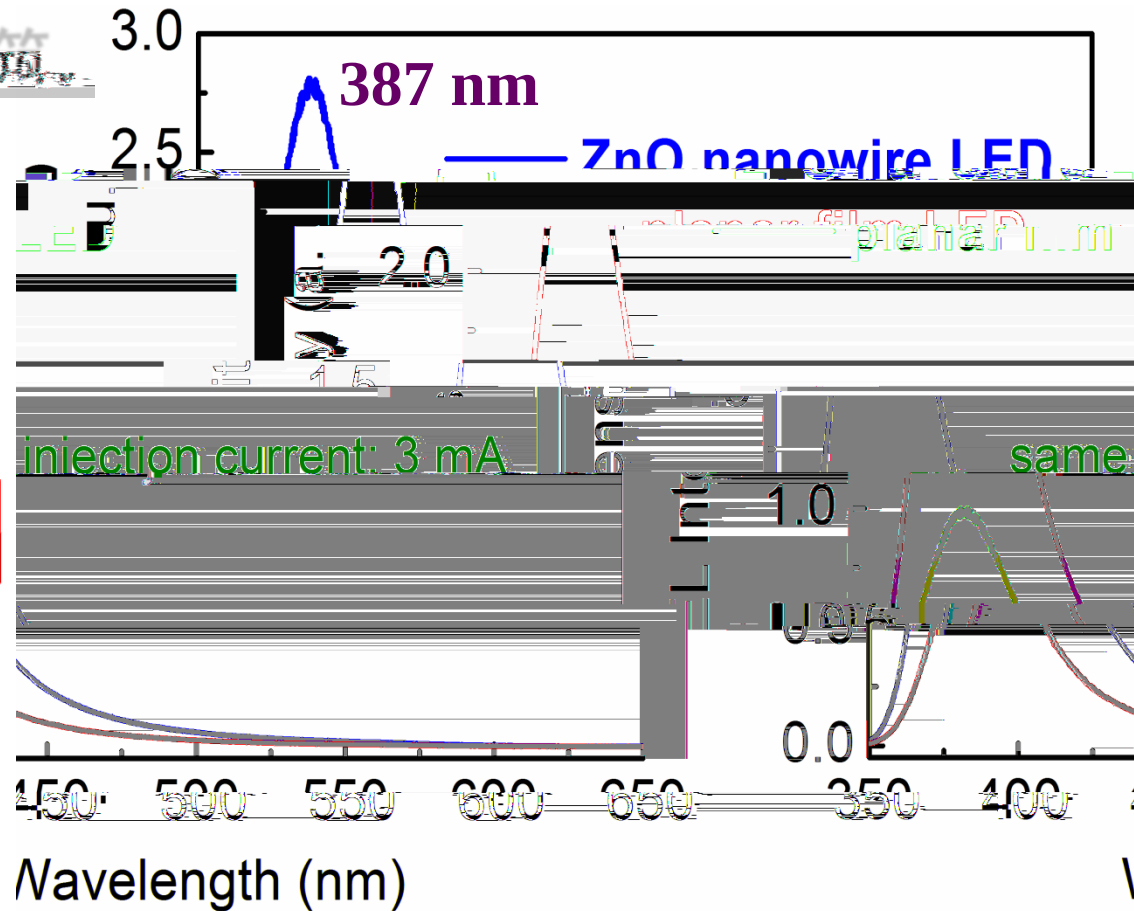
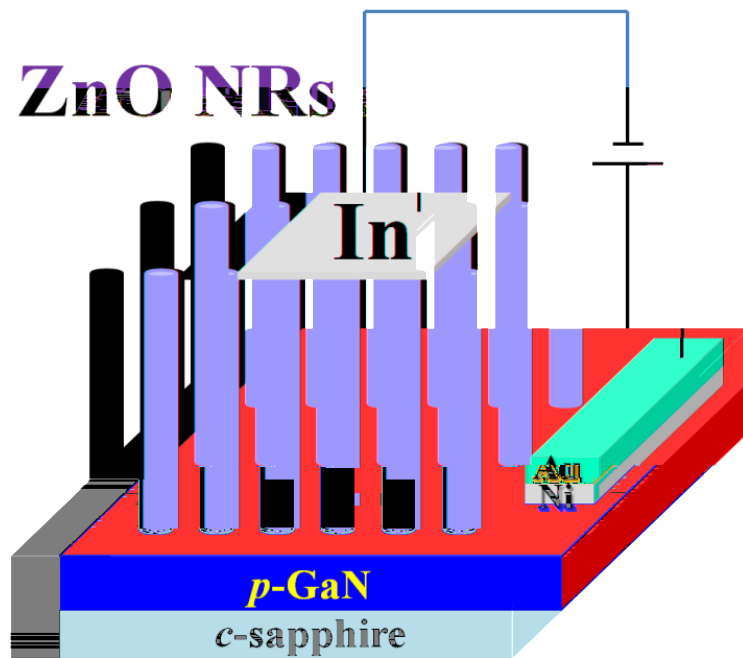
电子迁移率高于空穴，ZnO电子向GaN注入并辐射复合产生GaN发射



Appl. Phys. B 80, 871 (2005)

研究工作--纳米线LED器件

ZnO 纳米线 UV LED 的结构



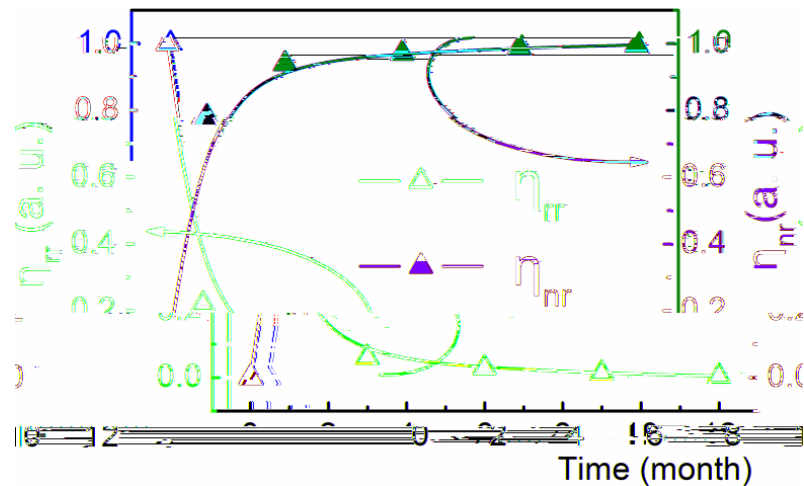
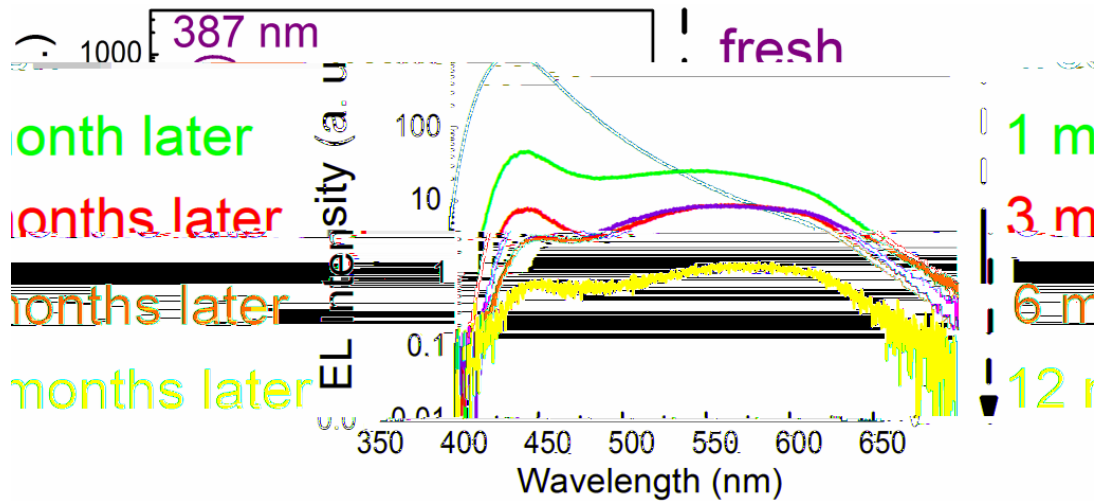
LED,

[*Appl. Phys. Lett.* 100, 203101 \(2012\)](#)

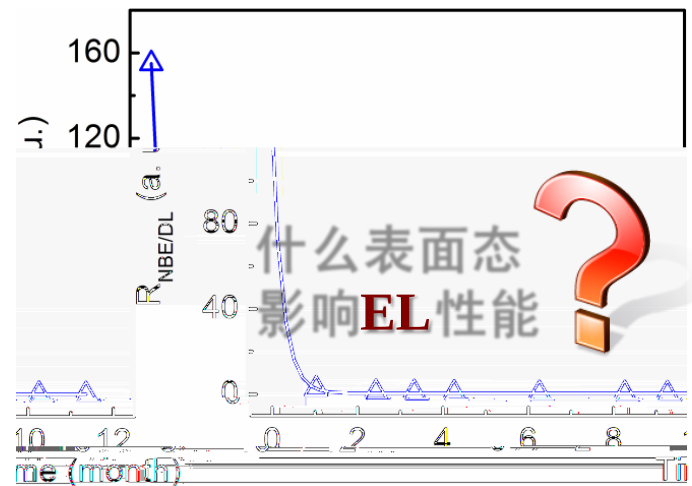
- 1.
- 2.
- 3.

研究工作--纳米线LED器件稳定性

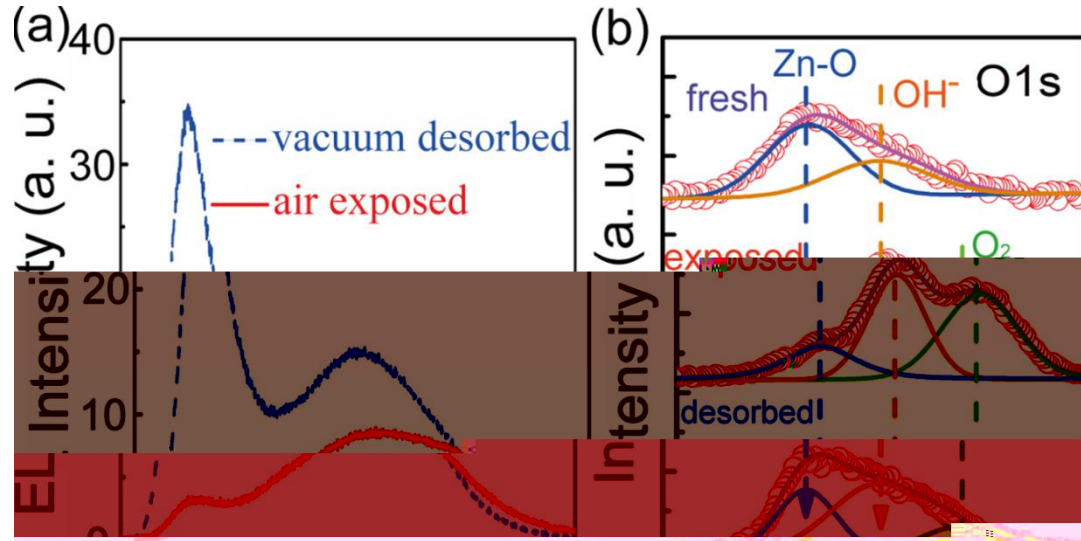
ZnO 纳米线 LED 的稳定性?



Appl. Phys. Lett. 100, 203101 (2012)



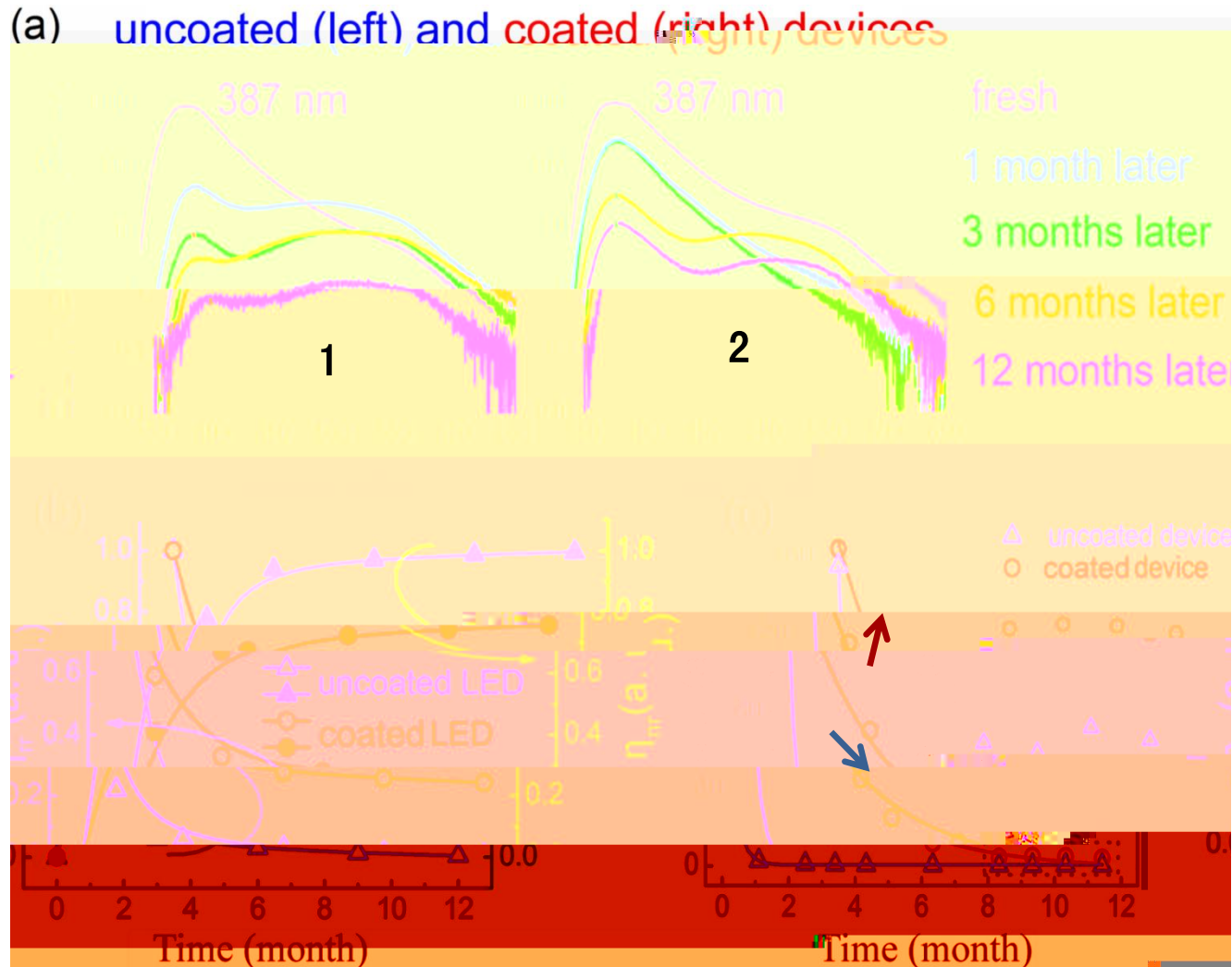
研究工作-器件: 纳米线器件稳定性



XPS
O₂
OH⁻

Media for Non-radiative & Deep-level Recombinations

研究工作--纳米线LED器件稳定性改进



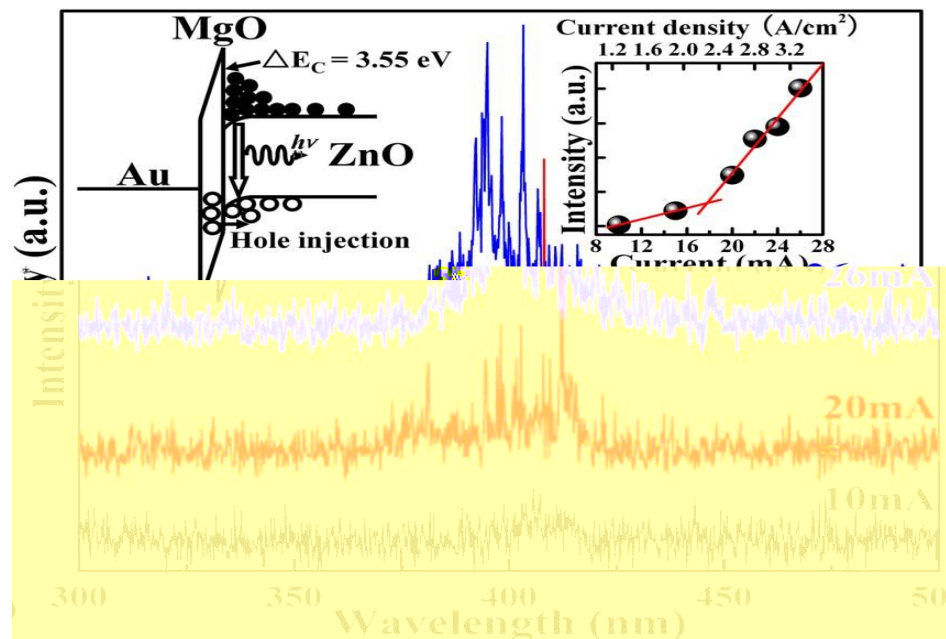
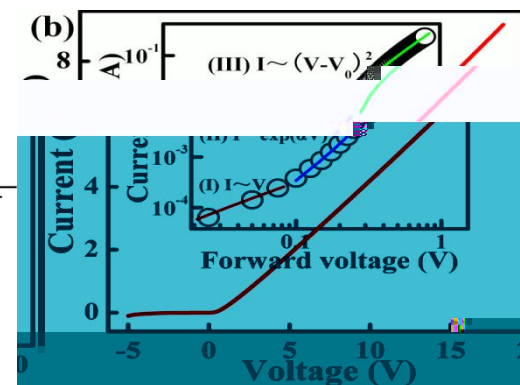
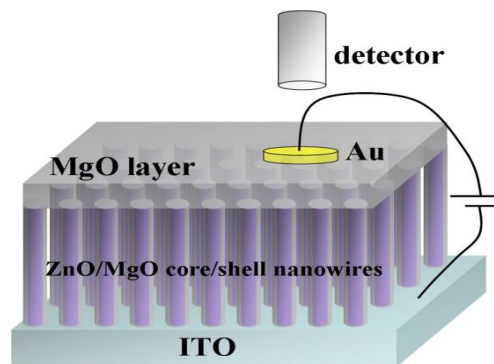
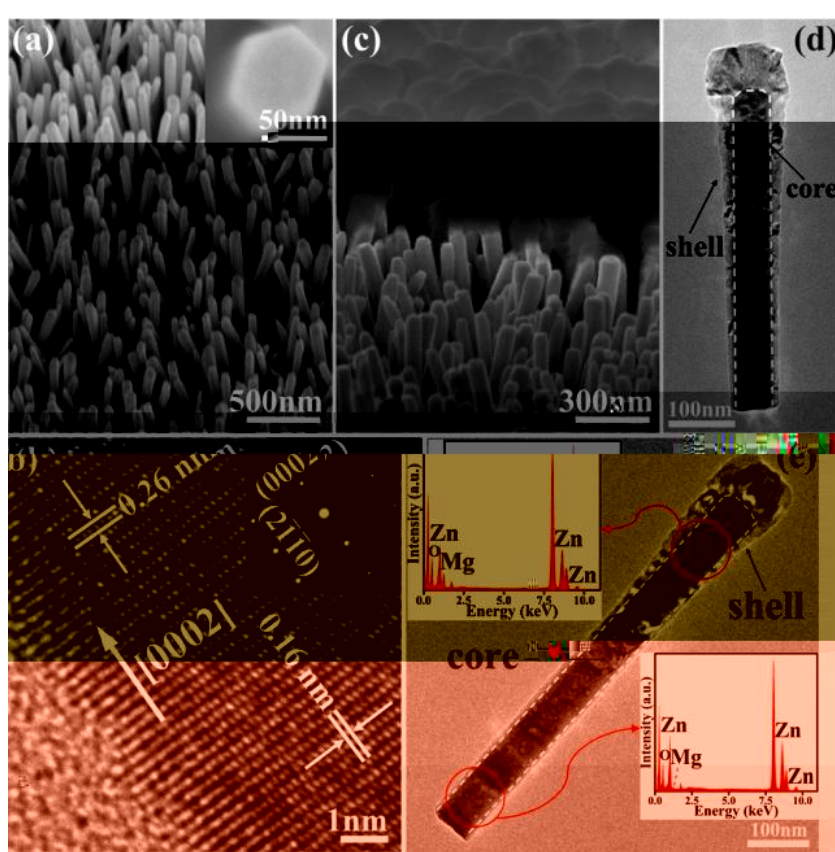
2 1

/

2 1

研究工作--纳米线LD器件

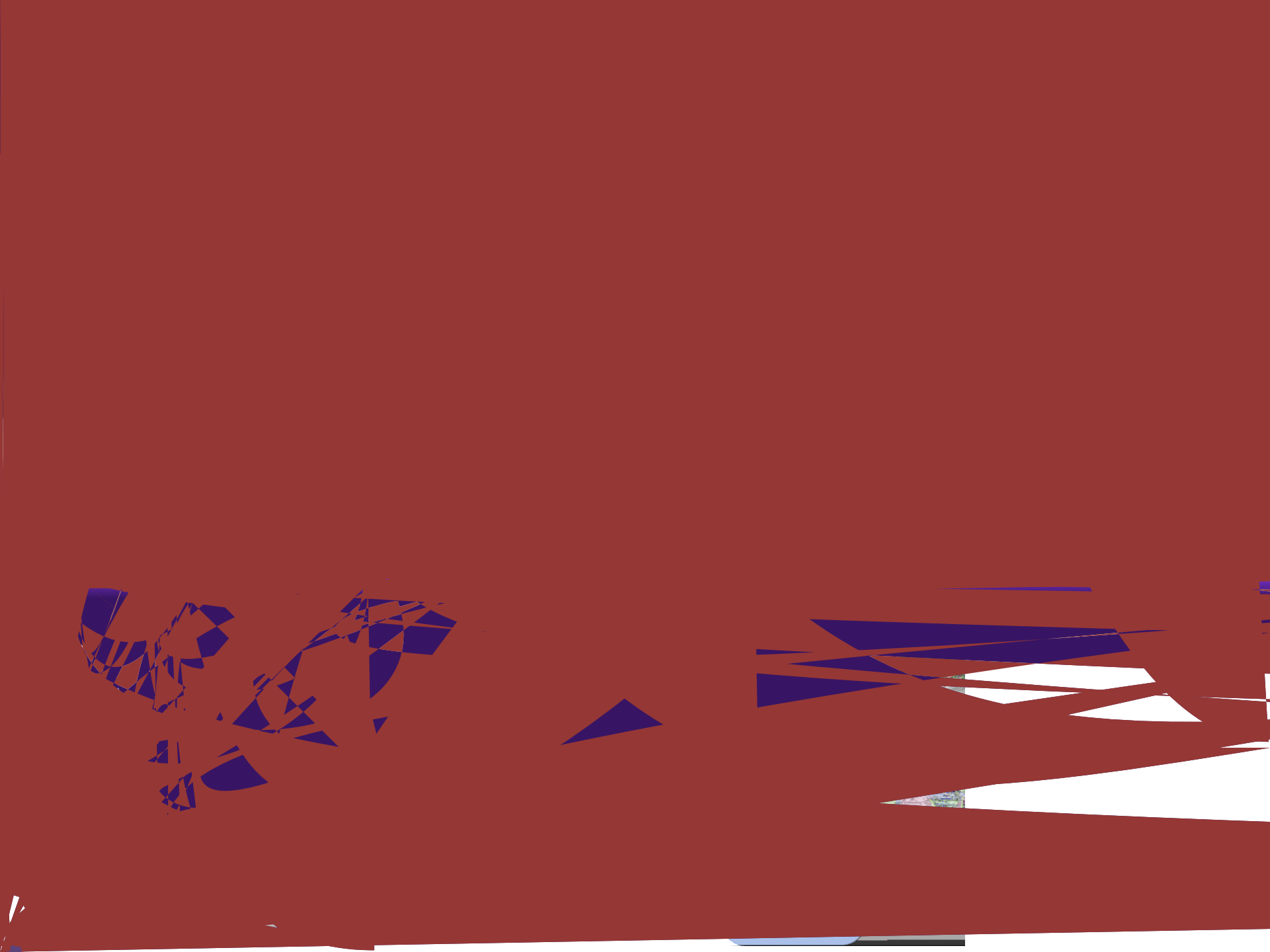
ZnO/MgO核壳纳米线MIS异质结LD



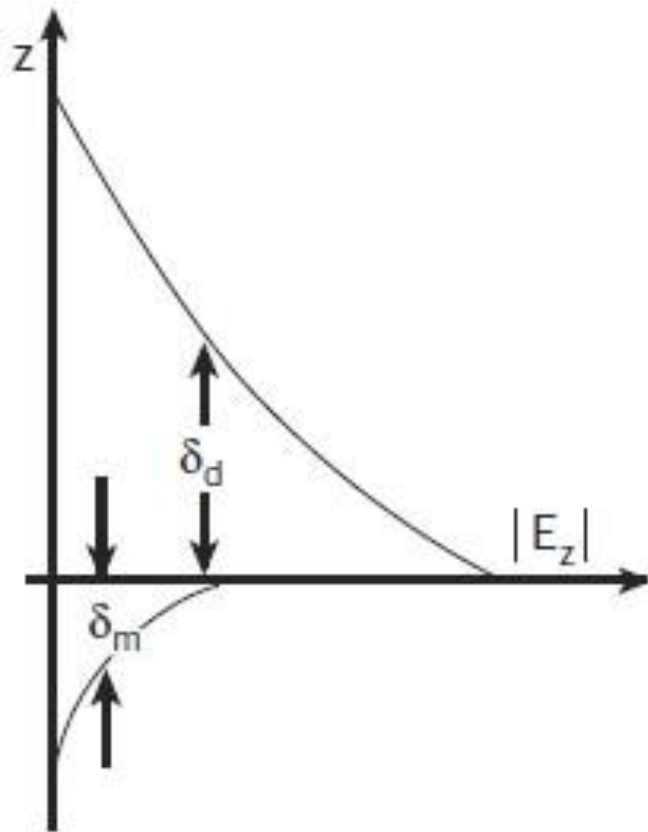
与薄膜器件相比：较低阈值电压

较高发射效率

Appl. Phys. Lett. 99, 063115 (2011)

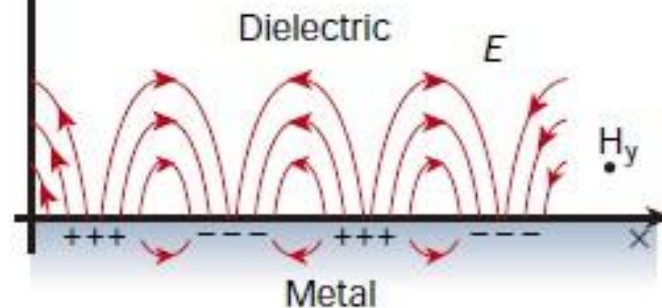


Surface Plasmon: collective oscillation mode of electrons at metal/dielectric interface

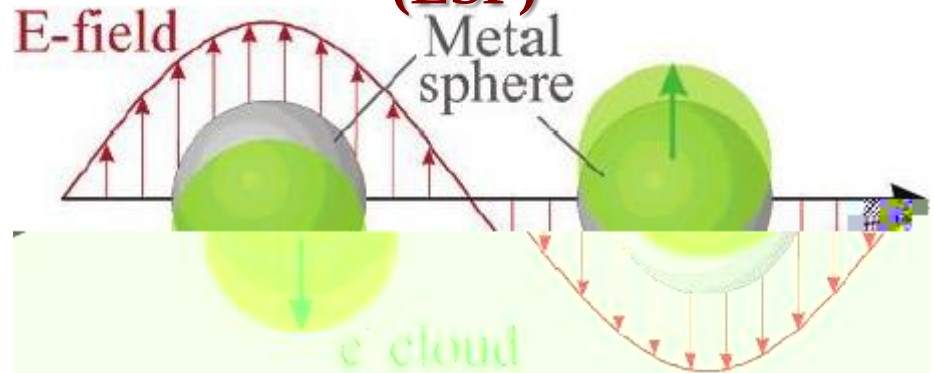


Evanescent wave:
Decay with the distance
from the metal surface

surface plasmon polariton
(SPP)

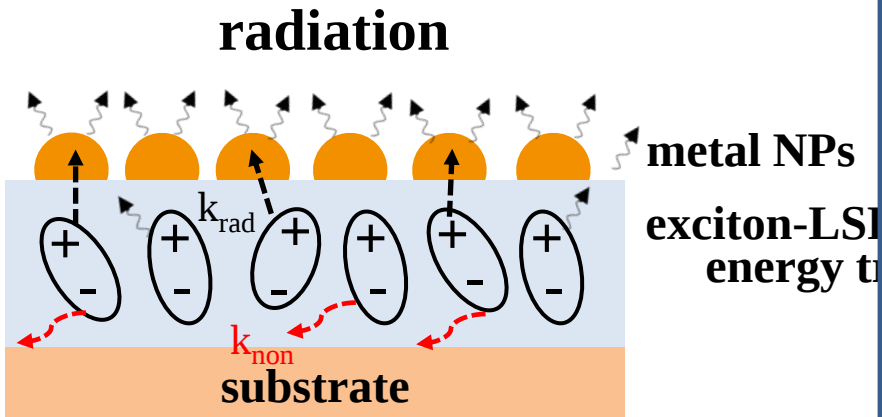
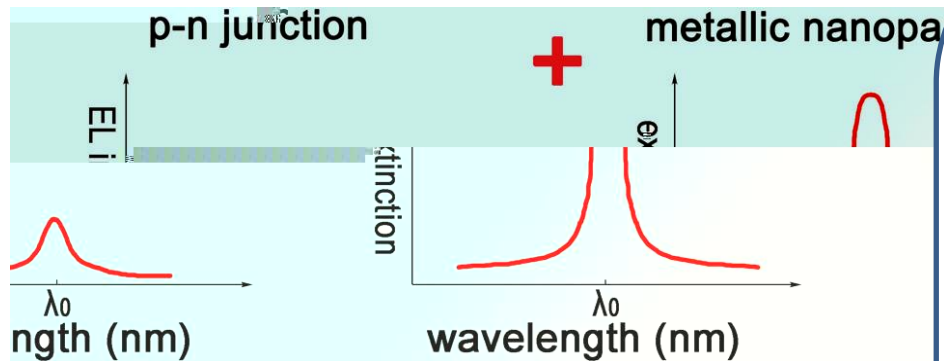
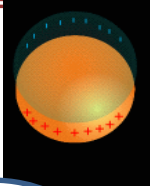
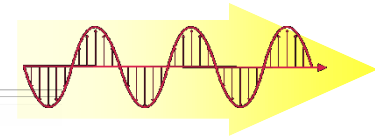


localized surface plasmon
(LSP)



Spectral enhancement: fluorescence spectrum,
Raman spectrum and nonlinear optical effect.

Mechanism for EL Enhancement



LSP-enhanced ZnO UV LED

Metal LSP + ZnO-based LED



Internal quantum efficiency (IQE) ↑

+

Light extraction efficiency (LEE) ↑



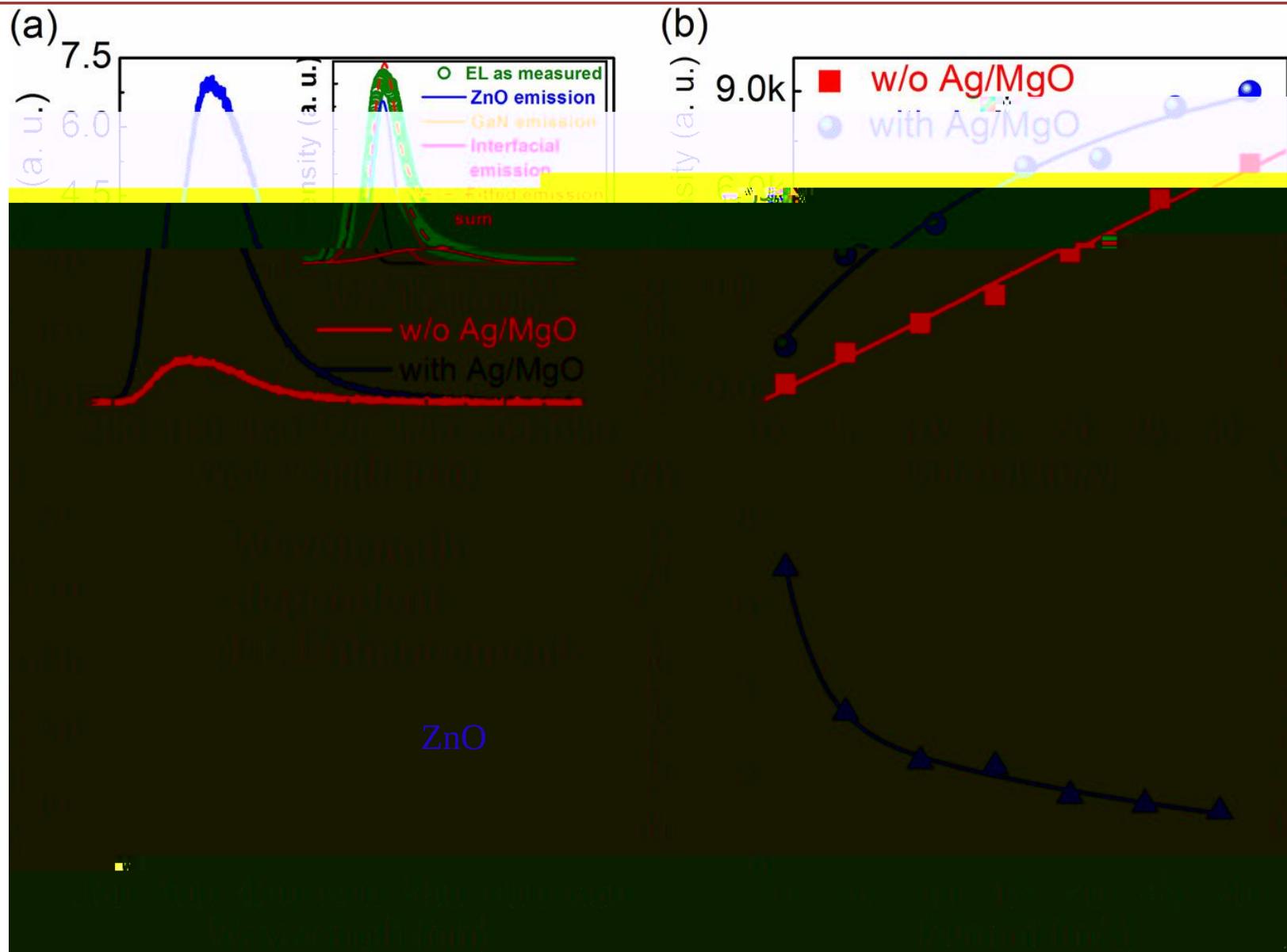
Enhanced EL performance

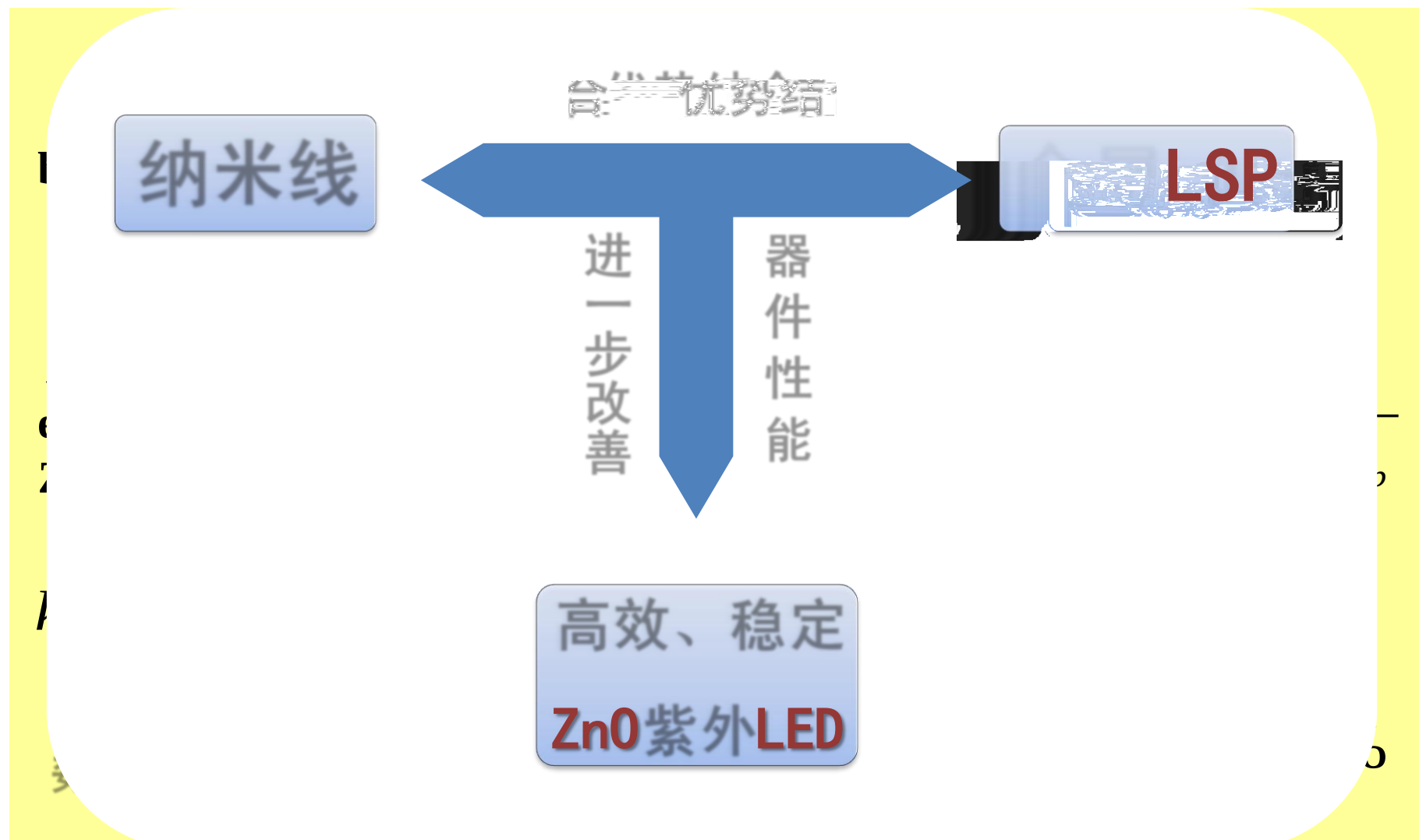
1.

FRET



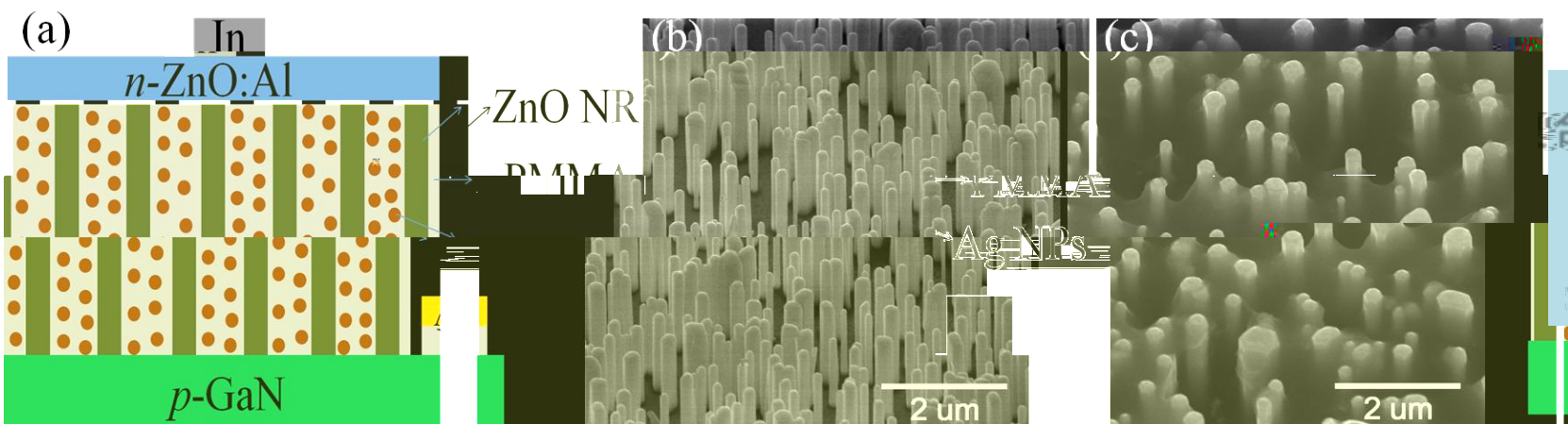
研究工作--LSP增强型平面LED器件



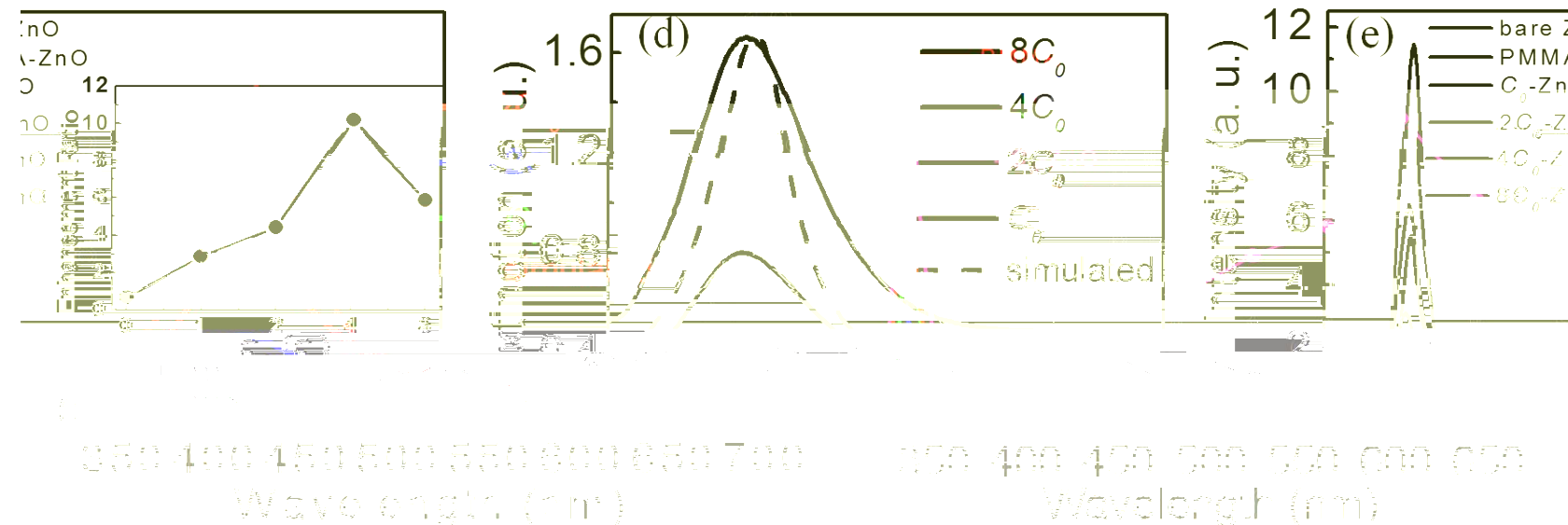


研究工作--LSP增强型、纳米线LED器件

Ag纳米粒子LSP增强的 ZnO 纳米柱阵列LED



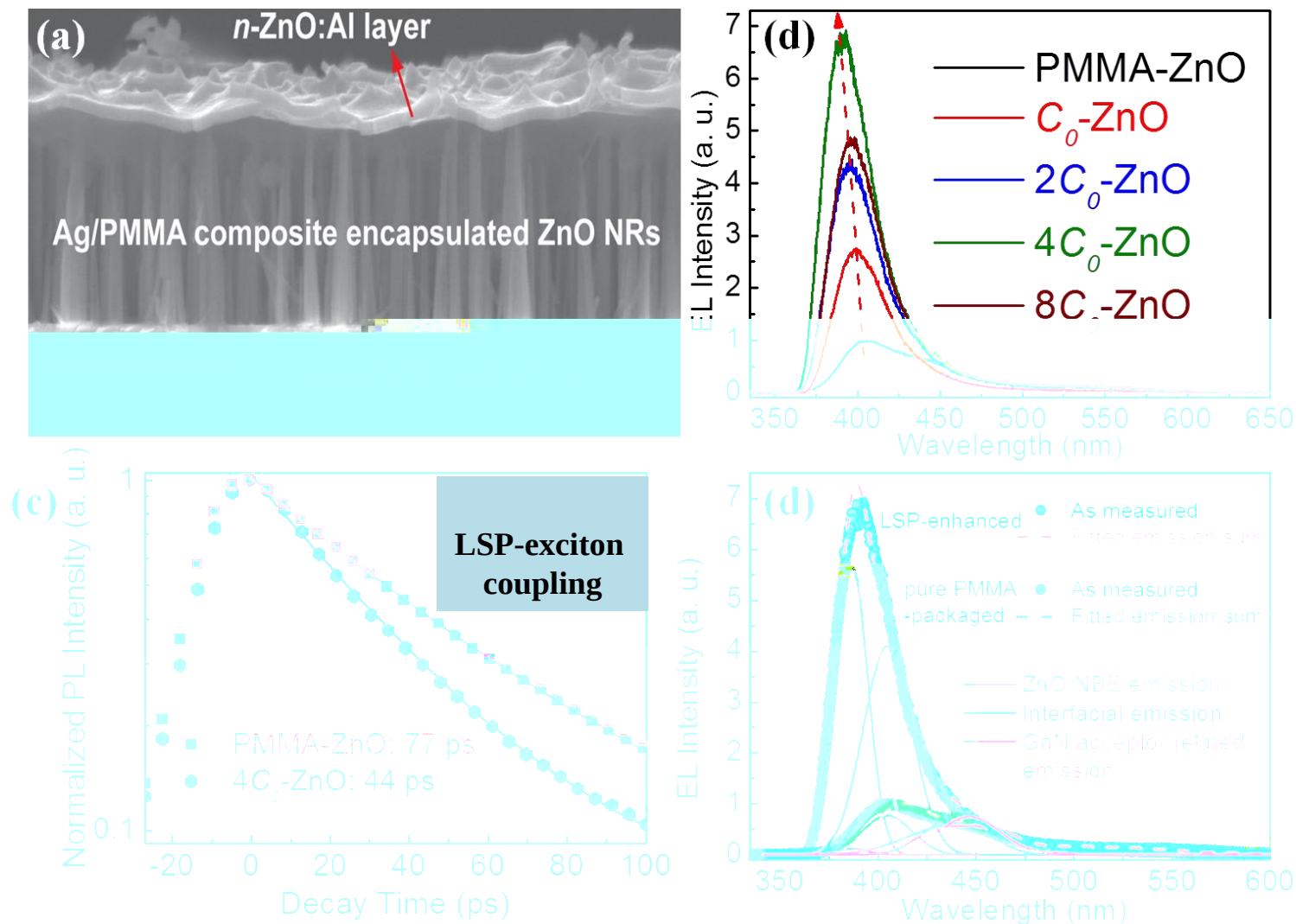
封装前
ZnO 纳
米柱阵列



不同浓度Ag粒子消光谱

优化浓度，PL最大11倍增强

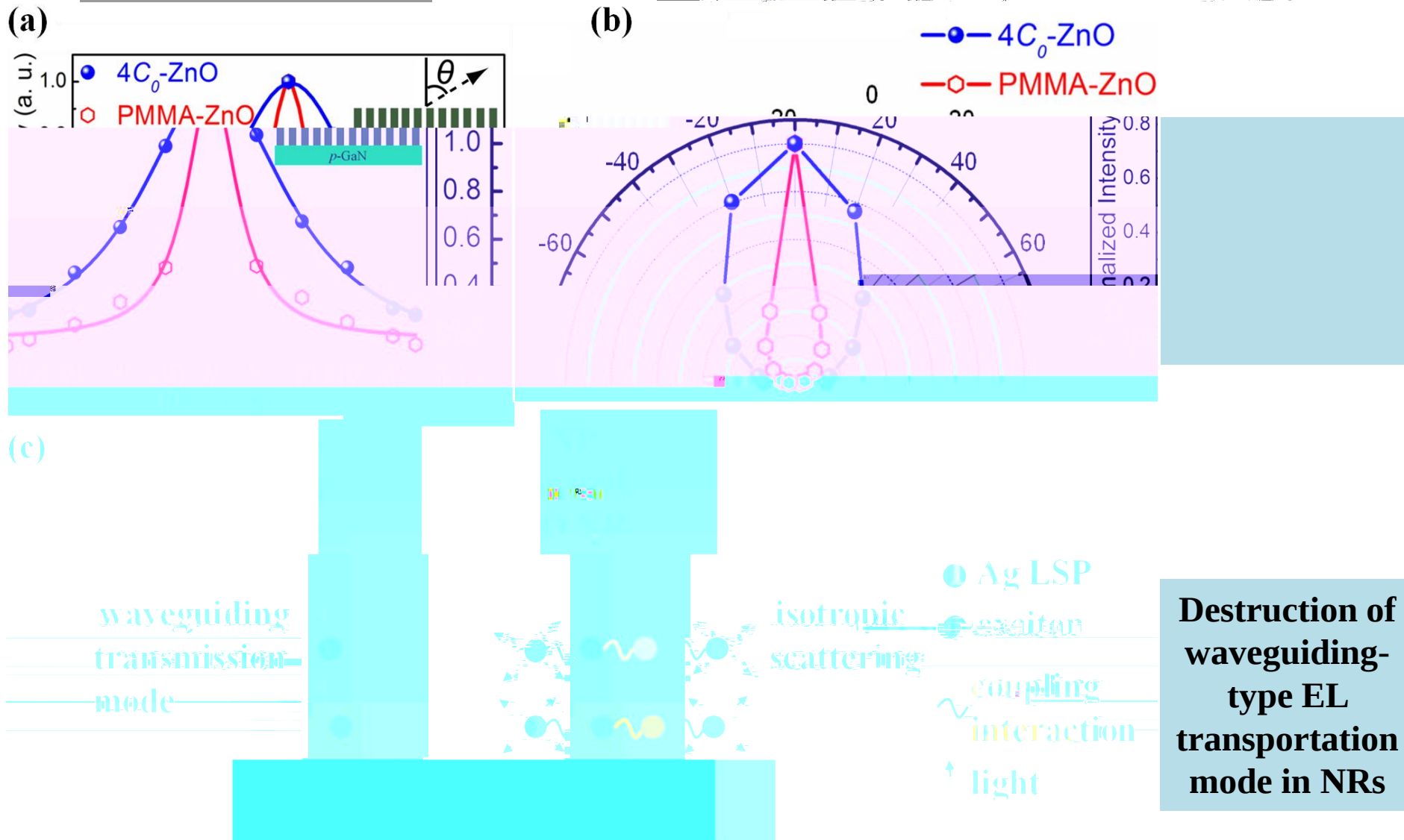
Exciton-LSP 近场耦合增强 ZnO 近带边EL



7
EL

ZnO

EL 空间分布展示: LSP-exciton coupling, LSP isotropic scattering



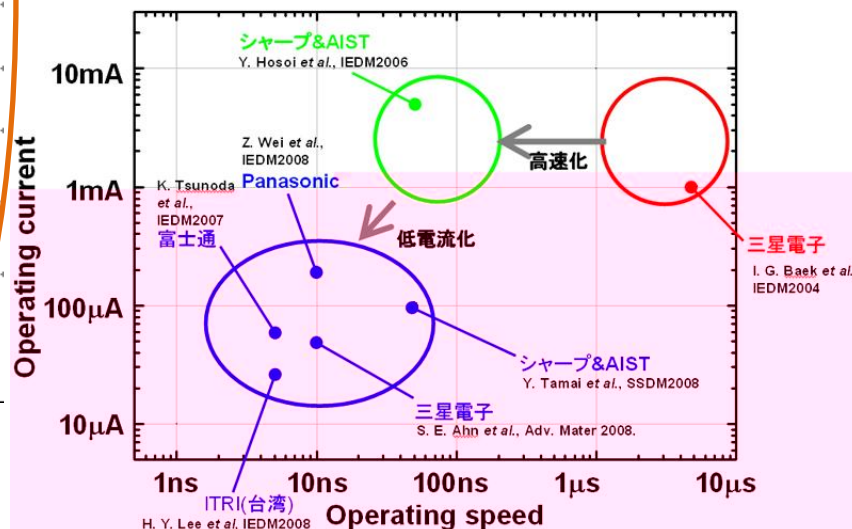
Resistive random-access memory (RRAM or ReRAM)

FeRAM MRAM PCRAM RRAM

存储器类型	NOR 闪存	NAND 闪存	铁电存储器	磁阻存储器	相变存储器	阻变存储器
单元元件	1T ¹	1T ¹	1T1C ²	1T1R ²	1T1R ²	1T1R/1D1R ²
单元面积	9-11F ²	5F ²	12-22F ²	6-16F ²	5-16F ²	5-8F ²
读电压	2V ²	2V ²	0.9V-3.3V ²	1.5V ²	3V ²	0.4V ²
读时间	10ns ²	50ns ²	45ns ²	20ns ²	60ns ²	<10ns ²
写电压	7-9V ²	15V ²	0.9-3.3V ²	1.5V ²	3V ²	0.5V-1V ²
写时间	1us/10ms ²	1ms/0.1ms ²	10ns ²	20ns ²	50/120ns ²	5-10ns ²
写能量	>1e-14 ²	>1e-14 ²	>3e-14 ²	>1.5e-10 ²	>6e-12 ²	>1e-12 ²
读写次数	>1e5 ²	>1e5 ²	>1e14 ²	>1e16 ²	>1e9 ²	>1e6 ²
保持时间	10 年 ²	10 年 ²	10 年 ²	10 年 ²	10 年 ²	10 年 ²
评论	/ ²	/ ²	与 CMOS 工艺不兼容, 存储密度较小 ²	与 CMOS 工艺不兼容, 写操作功耗大 ²	与 CMOS 工艺不兼容, 写操作功耗大 ²	与 CMOS 兼容性好, 研究时间短, 物理机理不明确 ²

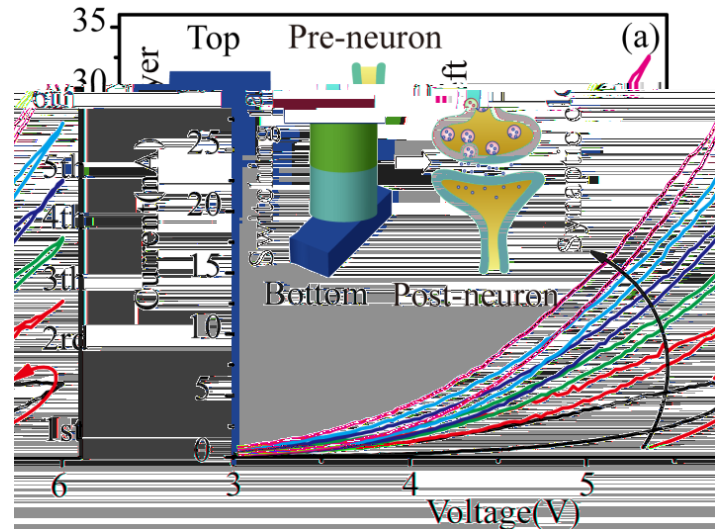
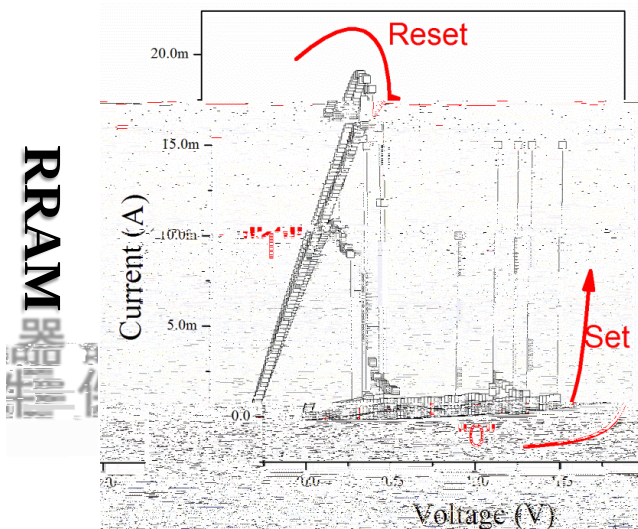
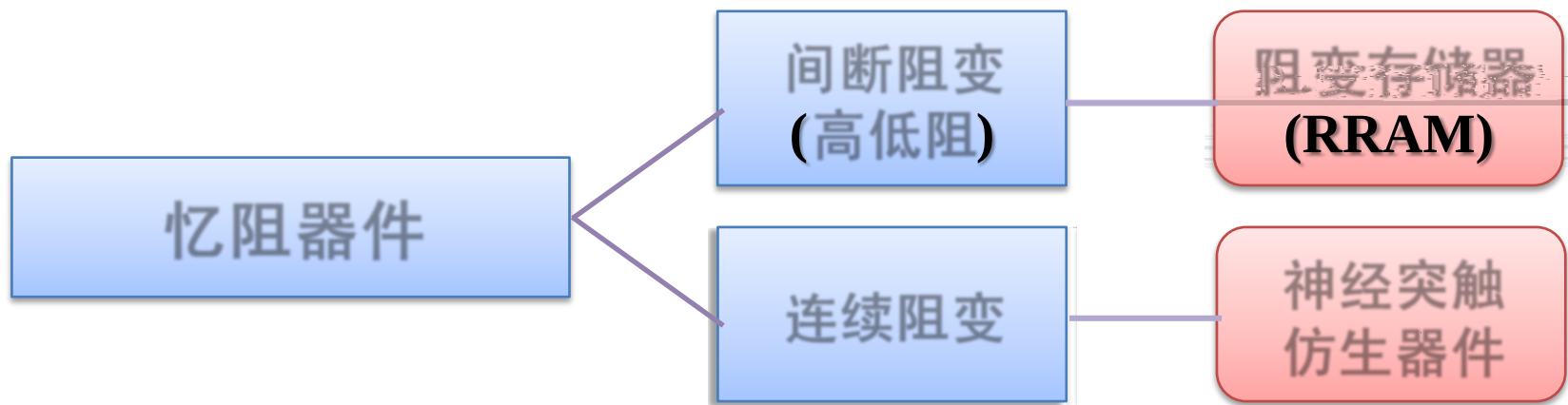
Parameter	Typical Flash	Target values
Switching element size (nm)	~100	~10
Access time (ns)	~10	~1
Write current (mA)	~10	~1
Write time (ns)	~10	~1
Read current (mA)	~10	~1
Read time (ns)	~10	~1
Endurance (cycles)	~10 ⁶	~10 ¹⁰
Retention (years)	~10	~10

RRAMの動作特性 (動作電流・速度)



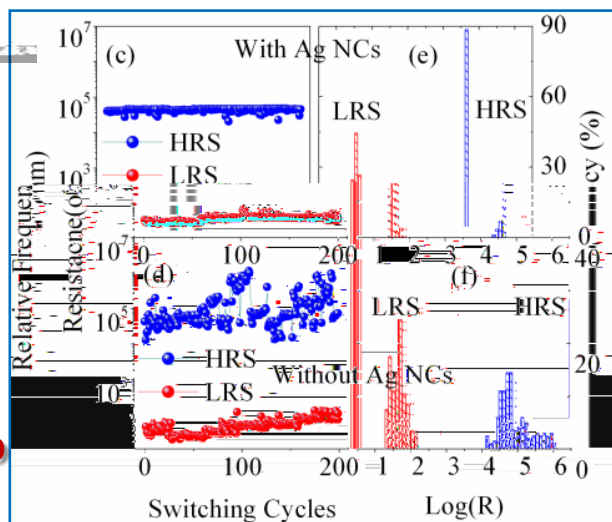
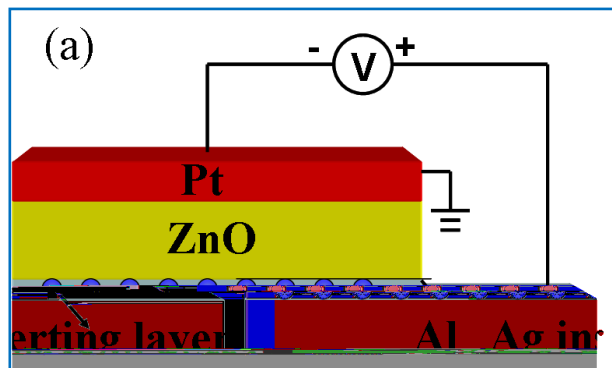
研究工作-ZnO基忆阻器件

ZnO材料:



神经突触仿生器件

引入**Ag**纳米晶层 $\longrightarrow$ 参数均一 + 高速转变(**20ns/30ns**)

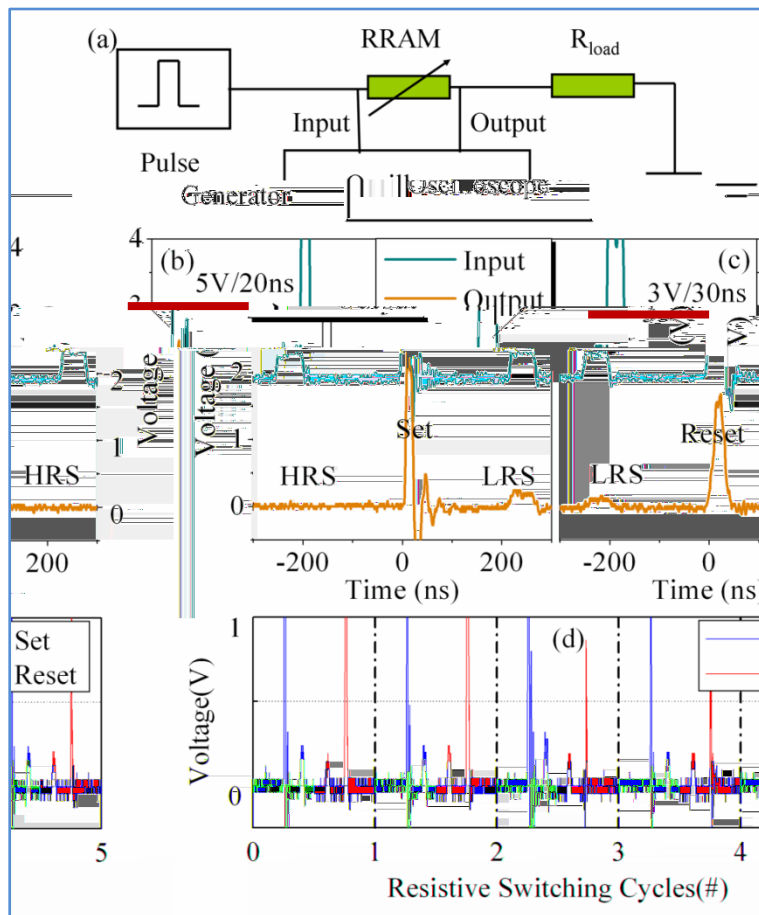


降低
高低阻波动

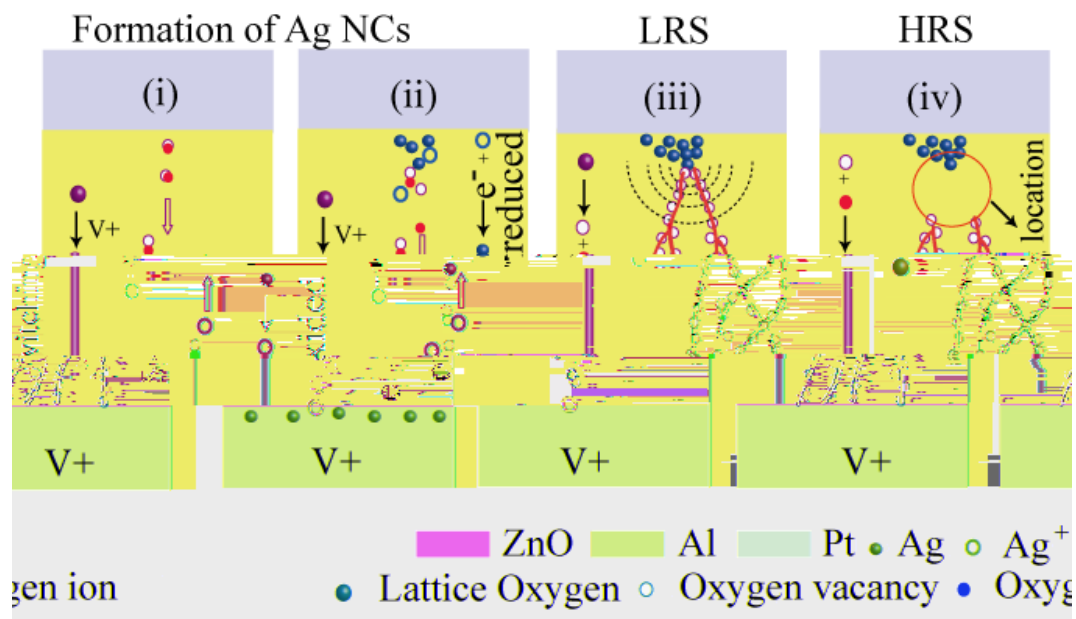
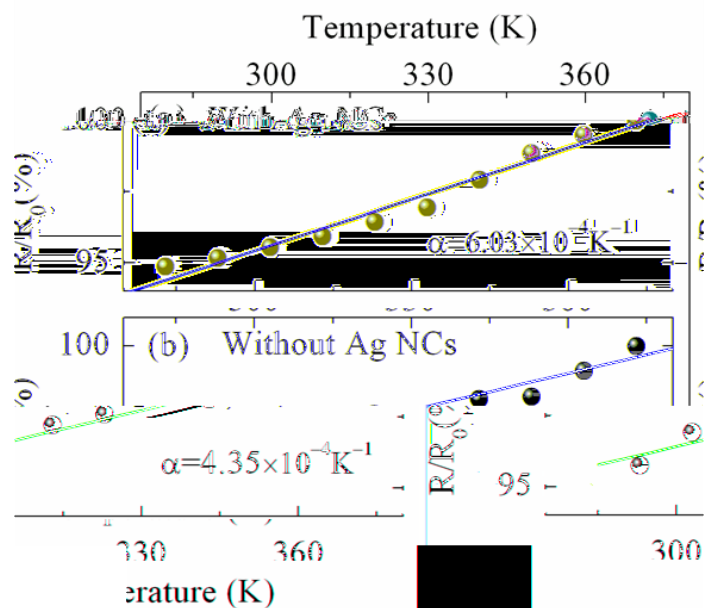
10%, 17%

↑

138%, 48%



研究工作——**ZnO RRAM**器件



氧空位缺陷 $\leftrightarrow$ 低阻态 (导电细丝)

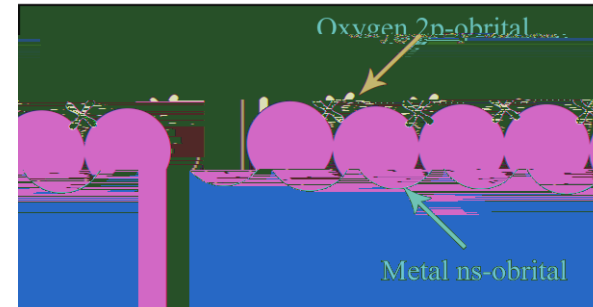
研究工作—透明柔性ZnO基RRAM器件

ZnO

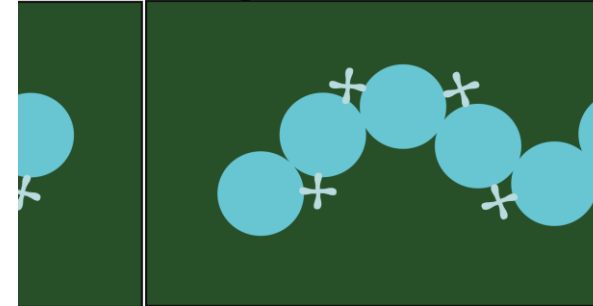
In, Ga

ZnO:In,Ga

Crystalline



Amorphous



In 5s



RRAM

研究工作—透明柔性ZnO基RRAM器件

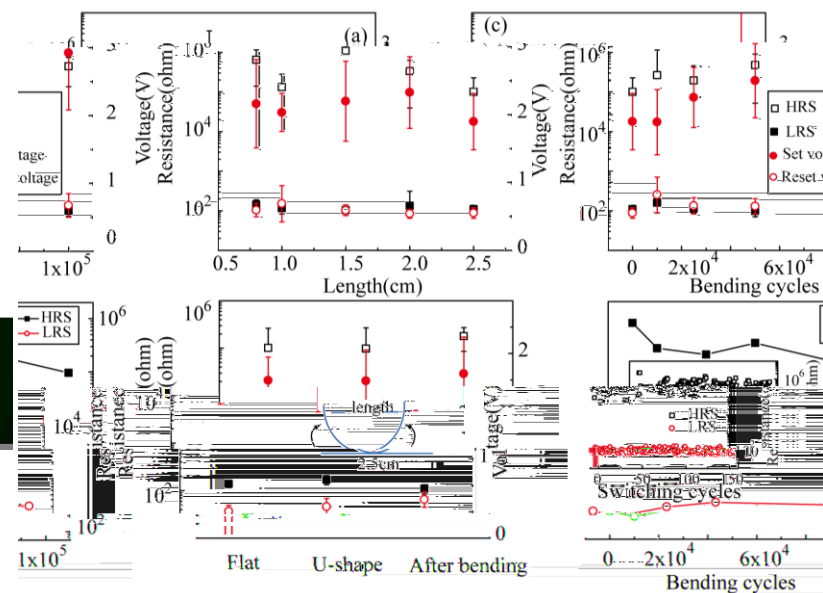
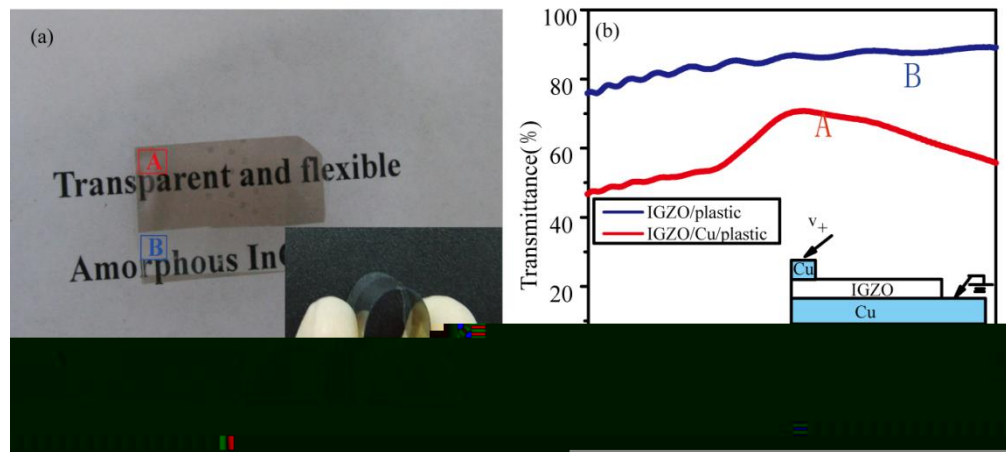
FT

InGaZnO

RRAM

FTRRAM?

10^5



IEEE Electron Device Letters 32, 1442 (2011)

: Memristor = Memory + Resistor
PC

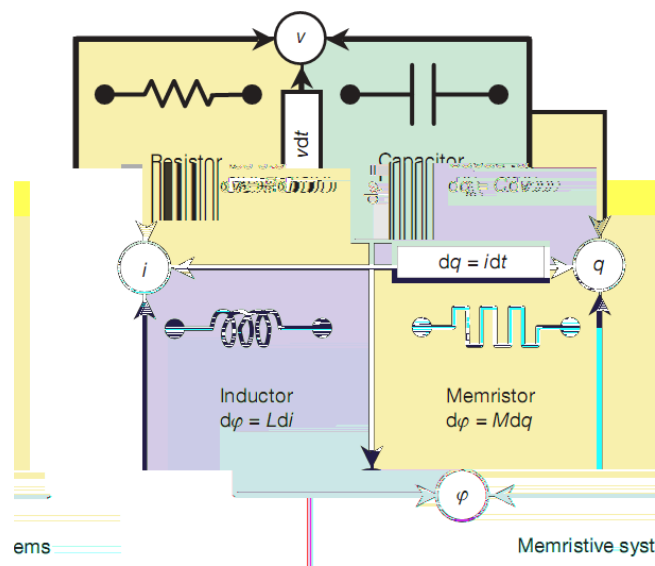
.....

1971

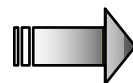
2008

HP

The Missing Memristor found



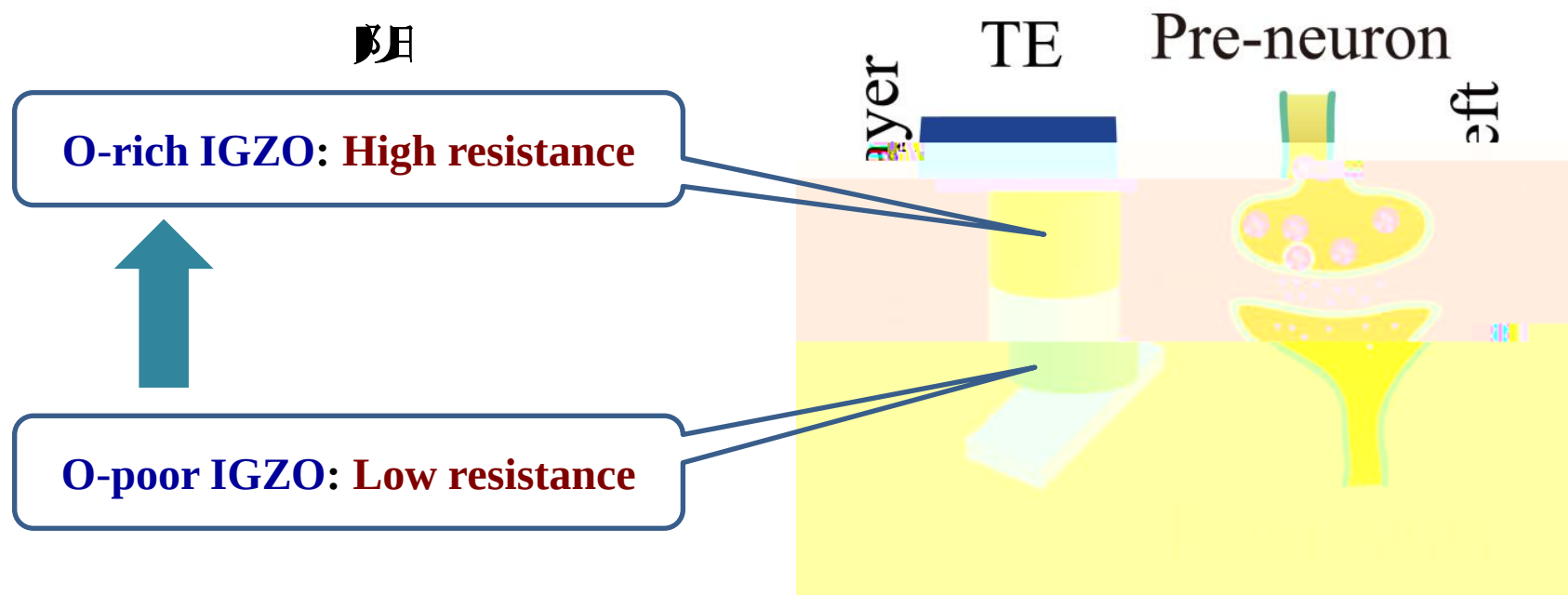
高度相似

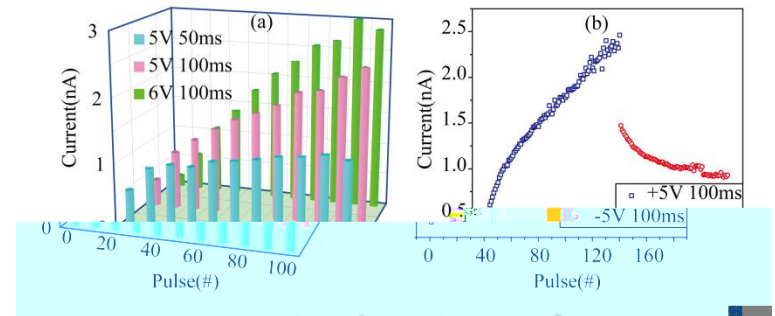


忆阻器：电阻阻值随流过的电荷量发生改变，并能够记住阻值的变化。

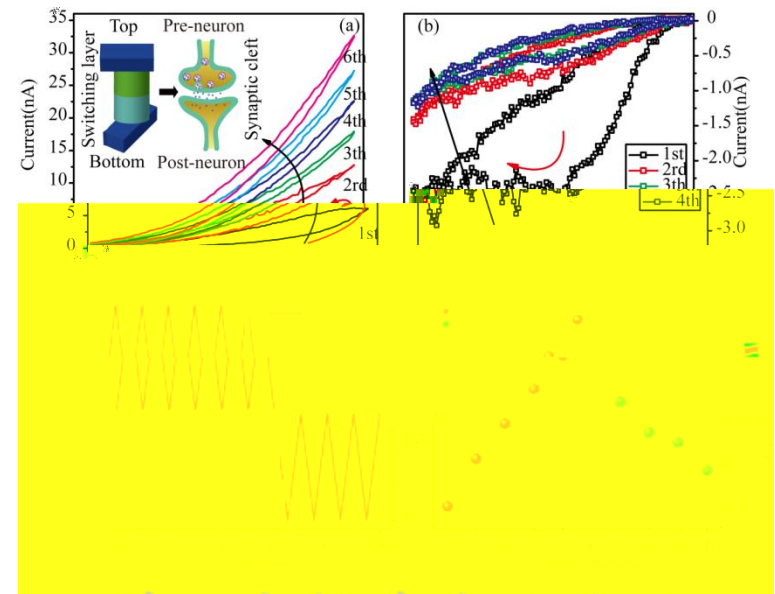
神经突触：连接状态随流经的离子而发生变化。

器件结构





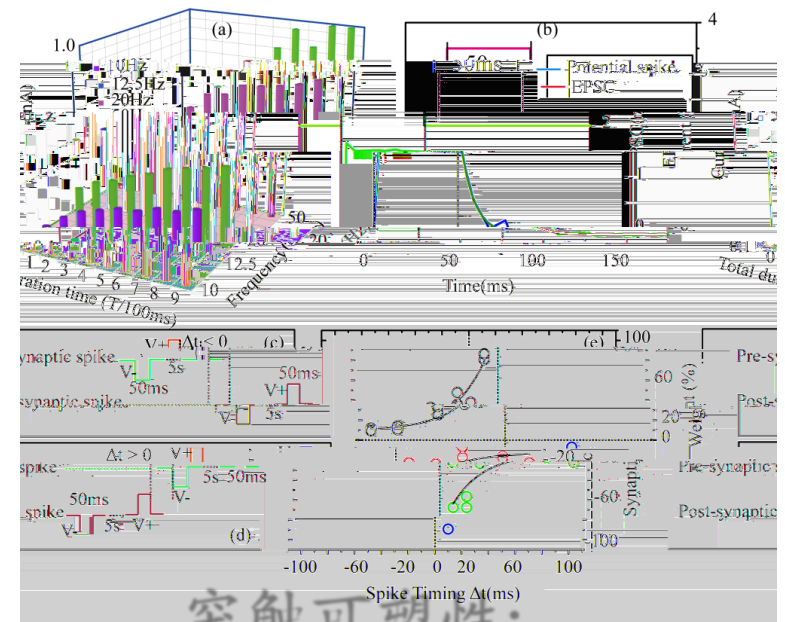
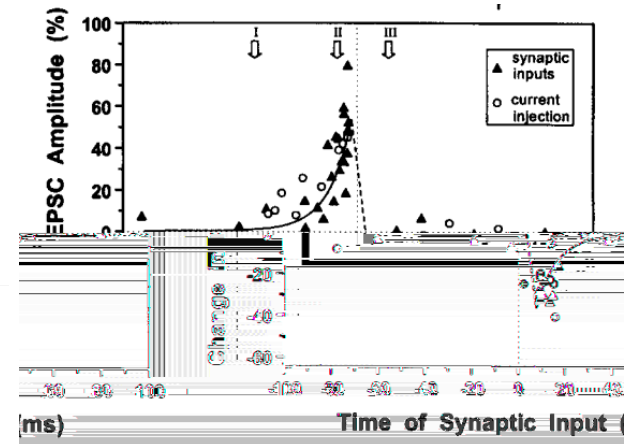
脉冲刺激特性



神经突触非线性传输

STDP

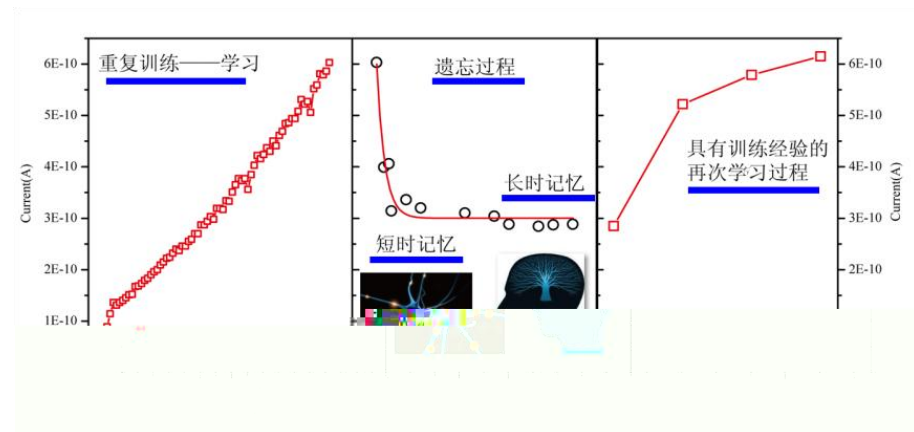
生物突触



突触可塑性:

频率特性及STDP功能

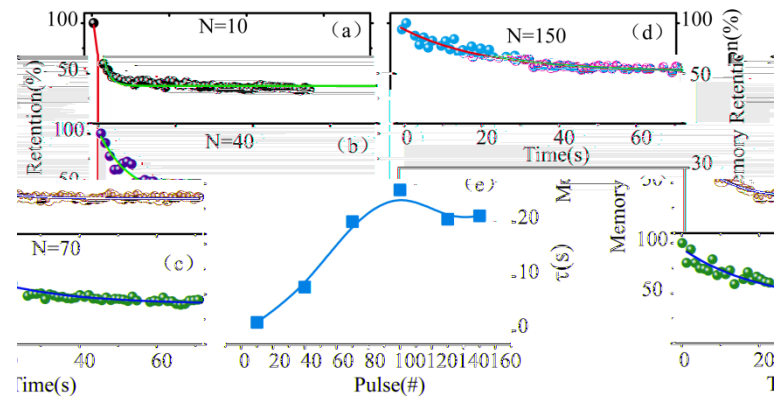
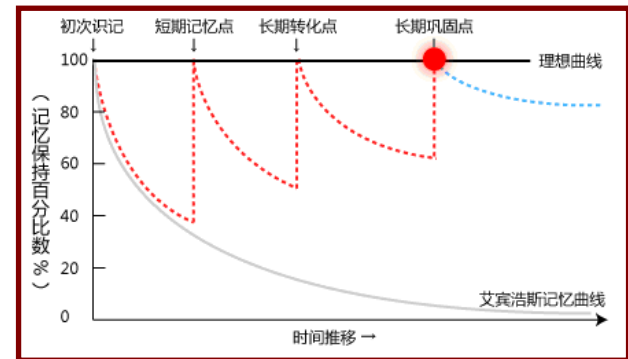
STDP



长短时记忆

及经验式学习行为

STDP

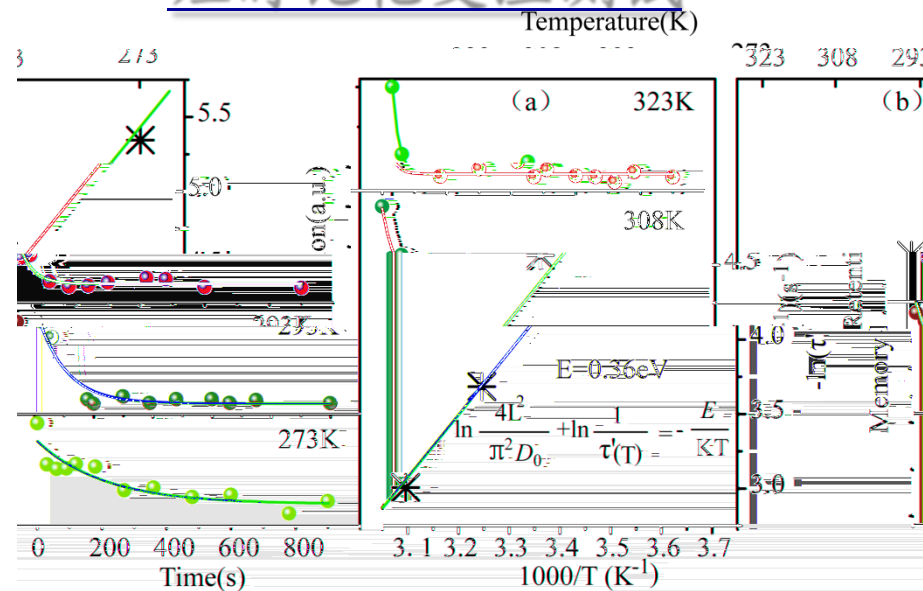


重复训练:

短时记忆向长时记忆的转化

STDP

短时记忆变温测试



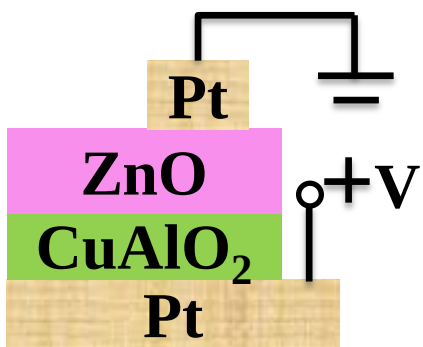
$$E=0.36\text{eV}$$

$$D=2.12 \times 10^{-14} \text{ cm}^2\text{s}^{-1}$$

$$E=0.4\text{eV}$$

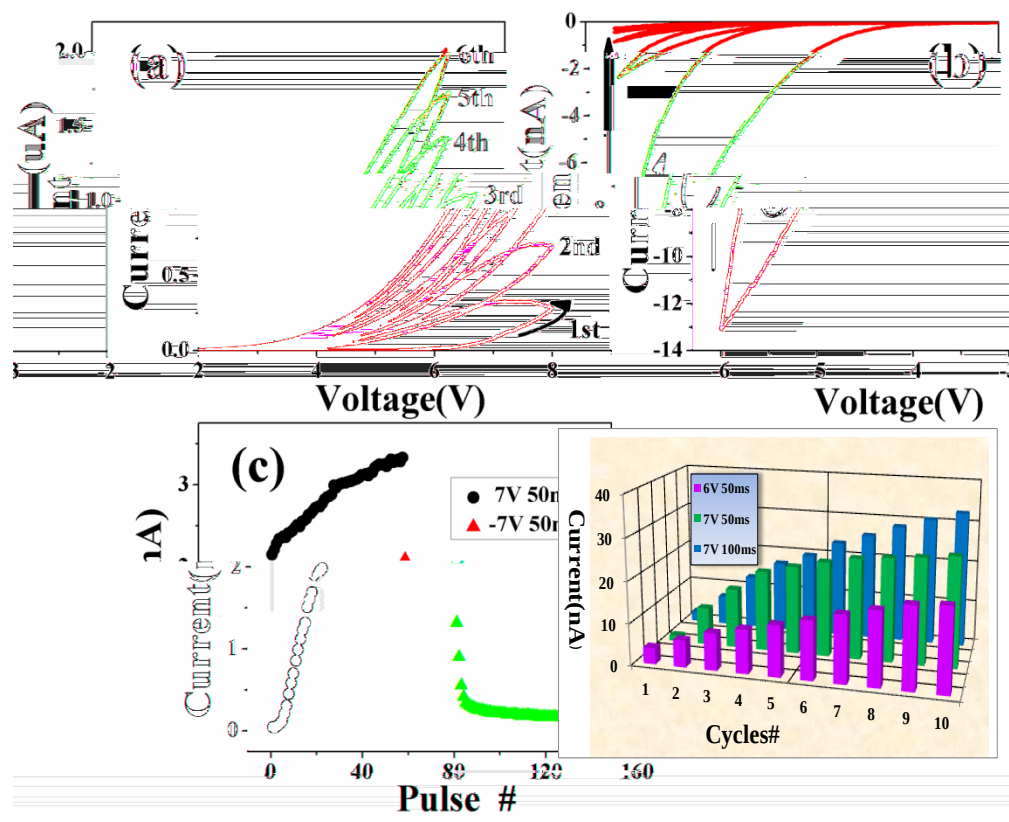
$$D=5 \times 10^{-14} \text{ cm}^2\text{s}^{-1}$$

研究工作——p-n结器件的基本忆阻特性

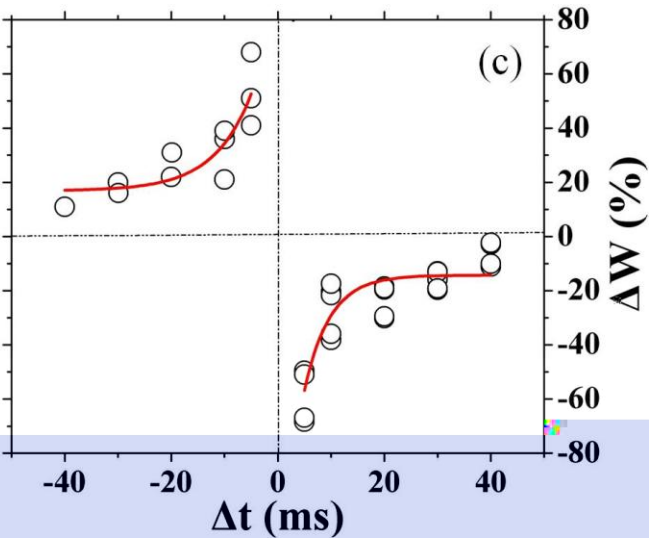
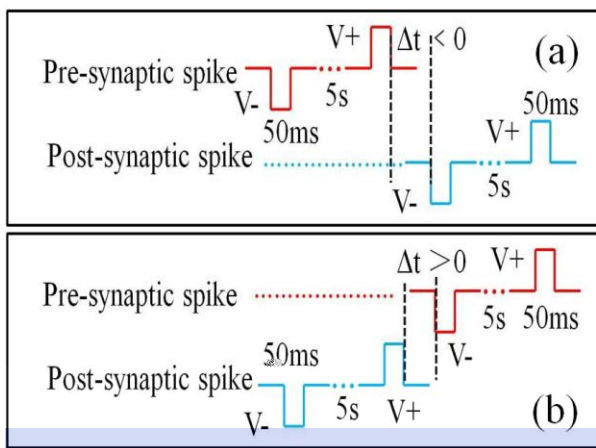


制备器件

择：惰性、减小势垒
择：惰性

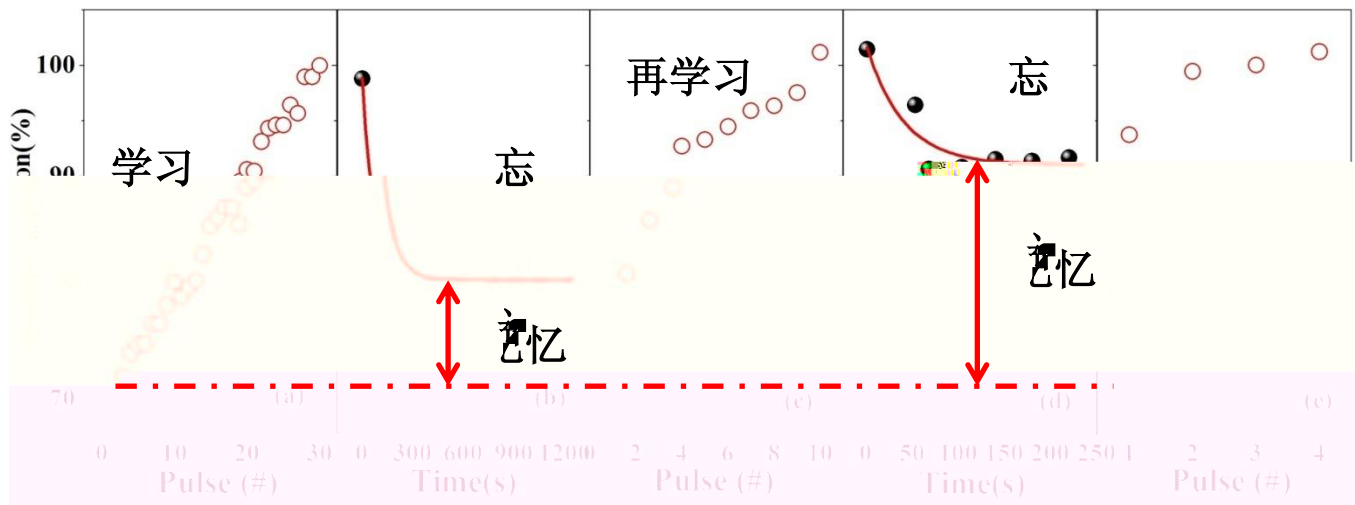


研究工作——p-n结器件的基本忆阻特性

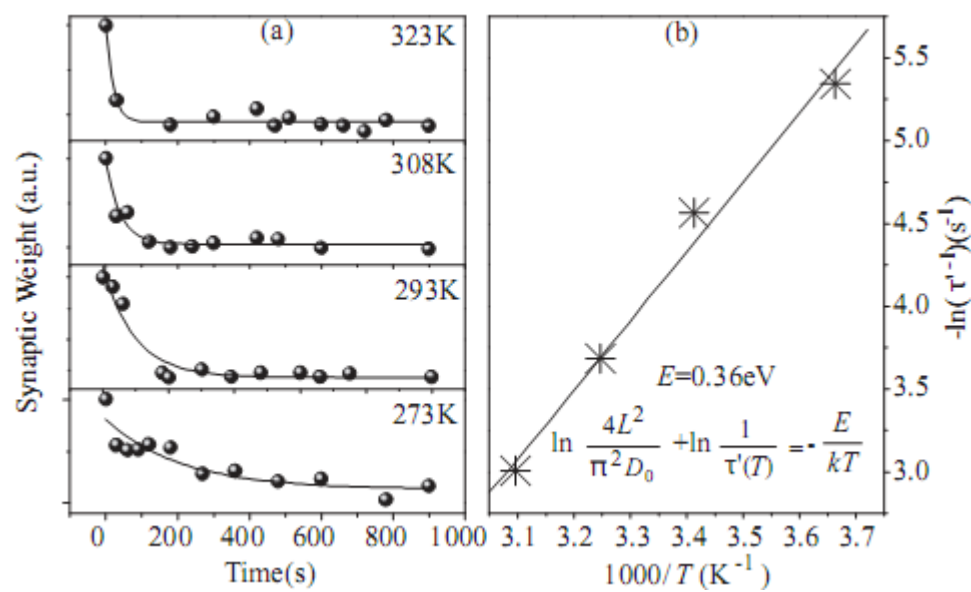


体现了 STDP 特性

忆阻器可以很好学习、遗忘



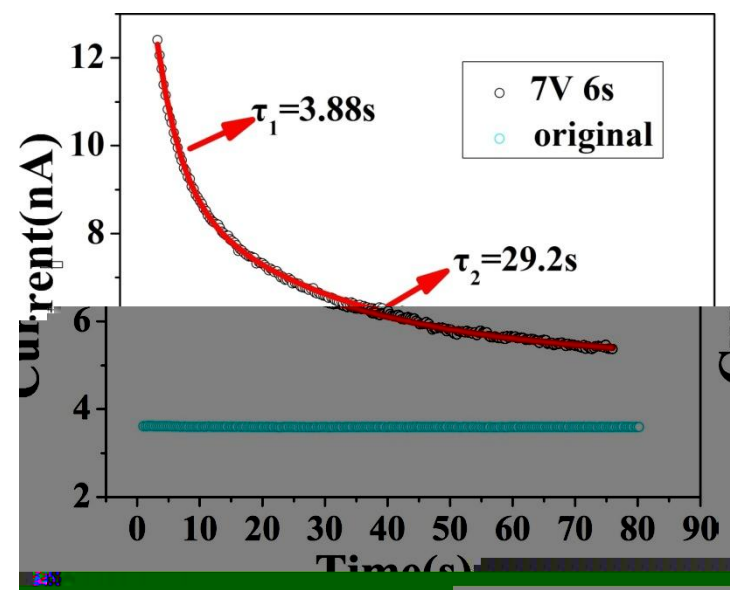
研究工作—p-n结器件的基本忆阻机制研究



IGZO双层忆阻器

$$I(t) = I_0 + A_1 e^{-t/\tau_1}$$

20-40s 弛豫时间
度差引 可于子回扩。

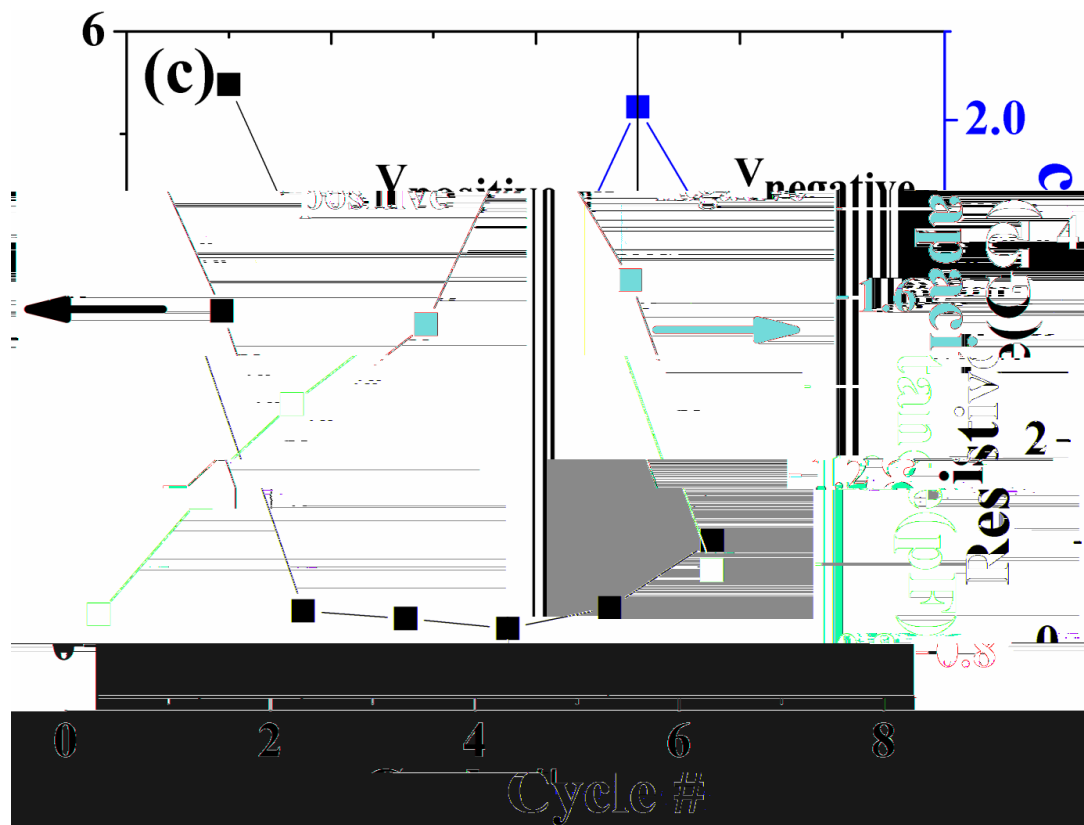


p-n 忆阻器

$$I(t) = I_0 + A_1 e^{-t/\tau_1} + A_2 e^{-t/\tau_2}$$

慢弛 快弛 可于 可于 度差
慢弛 快弛 可于 可于 度差

p-n 忆阻器会不同制



p-n 势垒 容

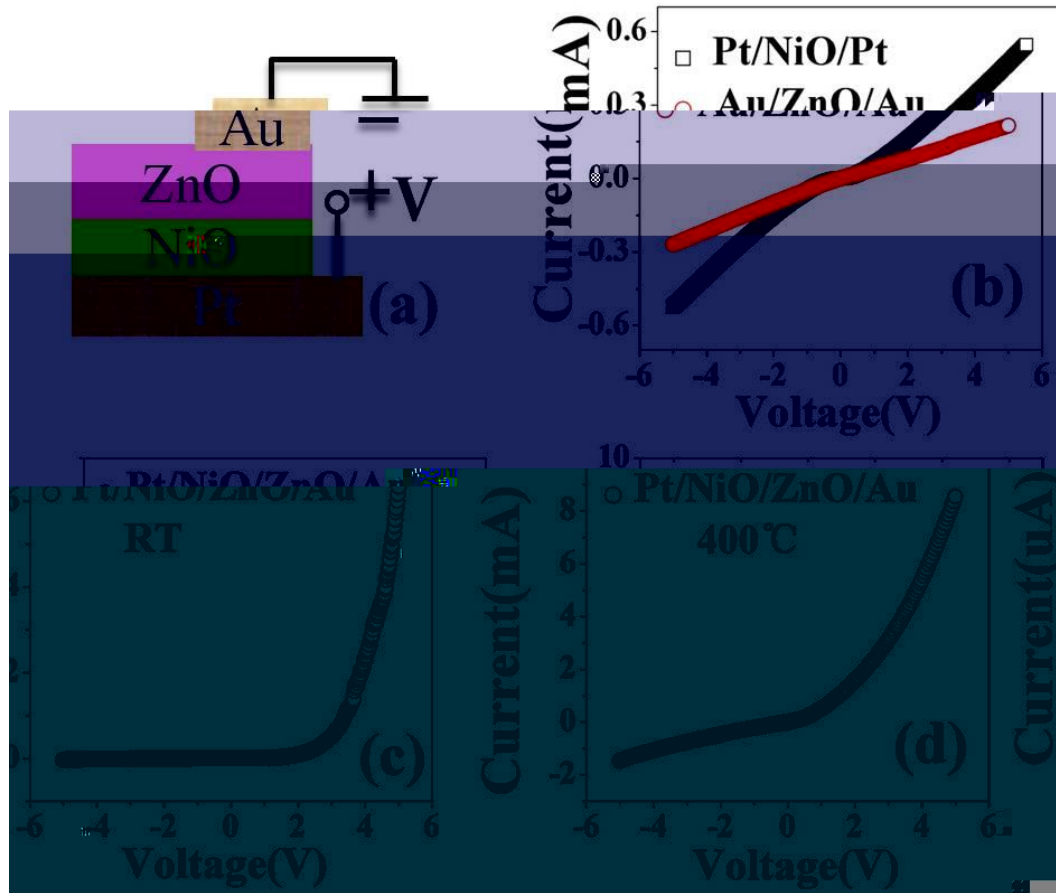
$$C_T = A_r \epsilon_0 / X_D$$

因：偏压下，势垒区变窄，减小，
反偏压下，势垒区变宽，增加。

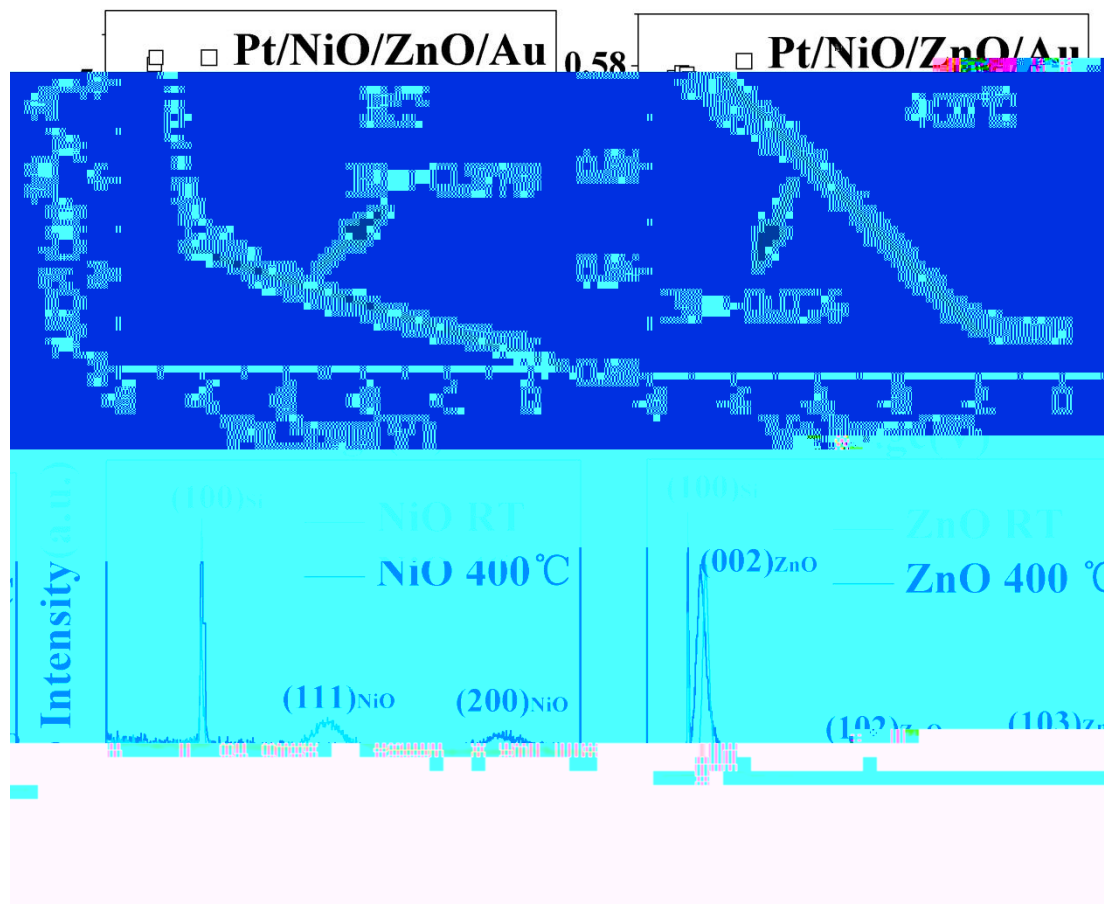
p-n

$$X_D = \sqrt{\frac{2\varepsilon_r\varepsilon_0(N_A + N_D)(V_D - V)}{qN_AN_D}}$$

p-NiO/n-ZnO



400 度 开启，
器件容 室 ZnO/NiO
在 -5V 到 5V
围内并
开启，我们
为 只 对势垒
宽度 所导
增加。

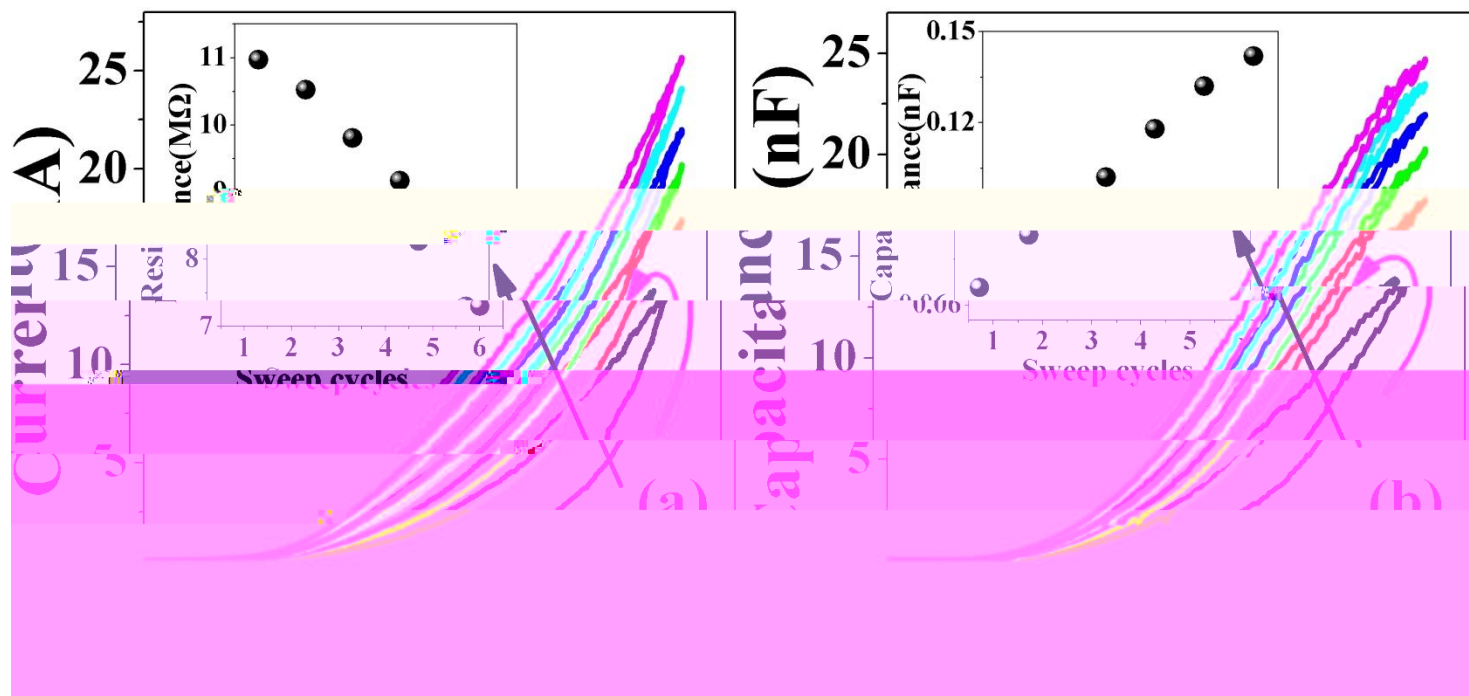


$$\frac{dC^{-2}}{d\phi} = -\frac{2}{q\epsilon_0\epsilon_r N_D A^2}$$

原因：于室，
性，对差，
又，外延关
，子在

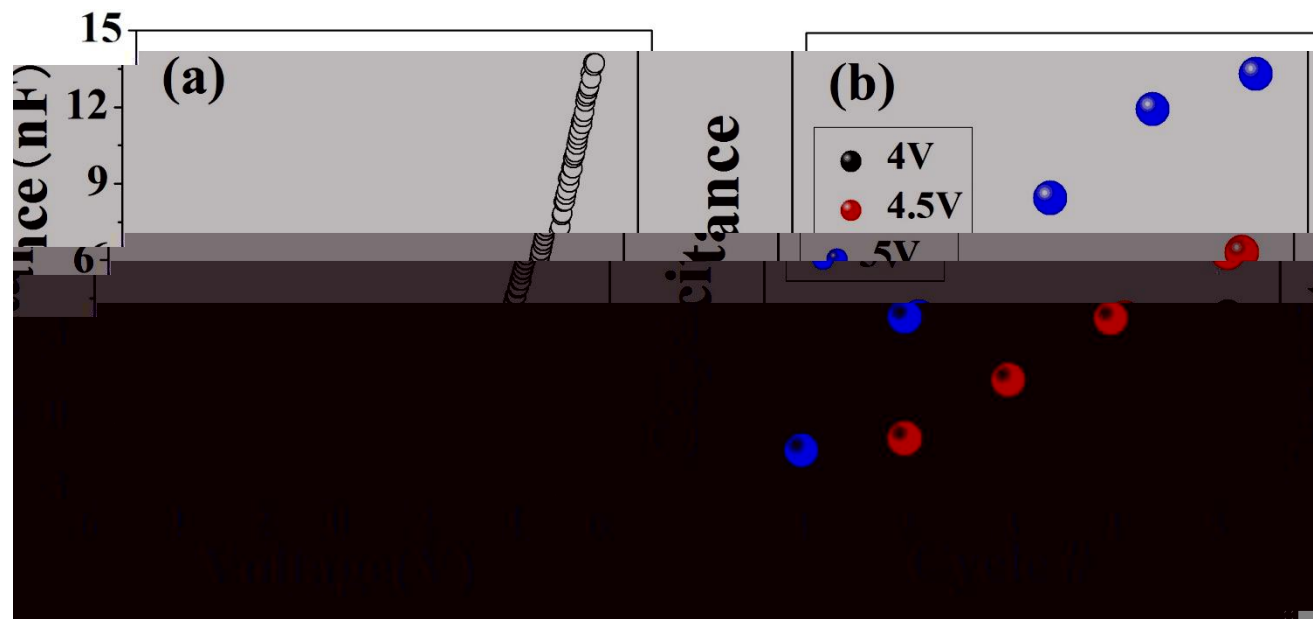
中富
一侧向
一侧扩，
导两度低。

400度，六 (002)峰与400度，
NiO (111)峰 外延关。



室对器件展了忆为，同实了
容忆，度下器件忆为。

使，或低，利于
子在势垒区，加利于实忆为。



为忆容器提供一思路

总结

ZnO

LED/LD

材料——

ZnO/MgZnO MgZnO/MgO /

器件——PIN MIS

p-GaN/i-ZnO/n-ZnO:Al Au/MgO(SiO₂)/ZnO

性能改善——

&LSP

ZnO

材料改性——

”

结构改进——

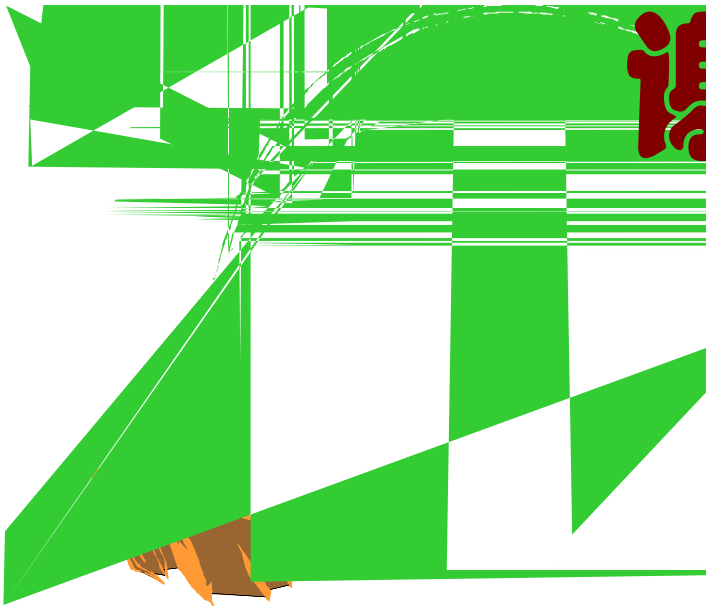
”

原理探索——

pn

”

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谢谢各位！